

1M x 16Bit CMOS Dynamic RAM with Fast Page Mode

DESCRIPTION

This is a family of 1,048,576 x16 bit Fast Page Mode CMOS DRAMs. Fast Page Mode offers high speed random access of memory cells within the same row. Power supply voltage (+5.0V or +3.3V), refresh cycle (1K Ref. or 4K Ref.), access time (-5, -6, or -7), power consumption (Normal or Low power) and package type (SOJ or TSOP-II) are optional features of this family. All of this family have $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh, $\overline{\text{RAS}}$ -only refresh and Hidden refresh capabilities. Furthermore, self-refresh operation is available in L-version.

This 1Mx16 Fast Page mode DRAM family is fabricated using Samsung's advanced CMOS process to realize high band-width, low power consumption and high reliability. It may be used as main memory unit for microcomputer, personal computer and portable machines.

FEATURES

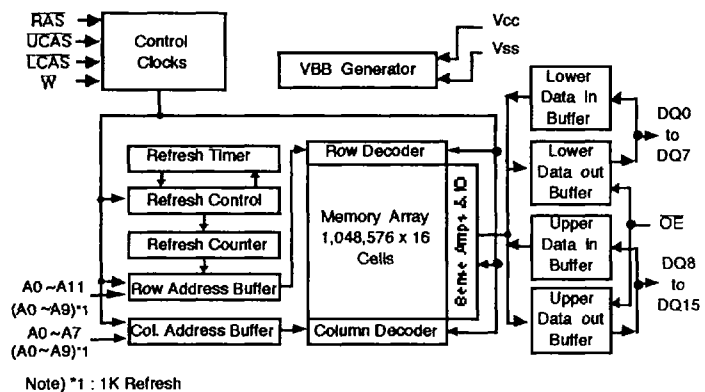
- Part Identification
 - KM416C1000B/B-L (5V, 4K Ref.)
 - KM416C1200B/B-L (5V, 1K Ref.)
 - KM416V1000B/B-L (3.3V, 4K Ref.)
 - KM416V1200B/B-L (3.3V, 1K Ref.)
- Active Power Dissipation Unit : mW

-5	396	576	605	880
-6	360	540	550	825
-7	324	504	495	770
- Refresh cycles

C1000B	5V	4K	64ms	128ms
V1000B	3.3V			
C1200B	5V	1K	16ms	
V1200B	3.3V			
- Performance range

-5	50ns	15ns	90ns	35ns	5V/3.3V
-6	60ns	15ns	110ns	40ns	5V/3.3V
-7	70ns	20ns	130ns	45ns	5V/3.3V
- Fast Page Mode operation
- 2 $\overline{\text{CAS}}$ Byte/Word Read/Write operation
- $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh capability
- $\overline{\text{RAS}}$ -only and Hidden refresh capability
- Self-refresh capability (L-ver only)
- TTL(5V)/LVTTTL(3.3V) compatible inputs and outputs
- Early Write or output enable controlled write
- JEDEC standard pinout
- Available in Plastic SOJ and TSOP(II) packages
- Single +5V \pm 10% power supply (5V product)
- Single +3.3V \pm 0.3V power supply (3.3V product)

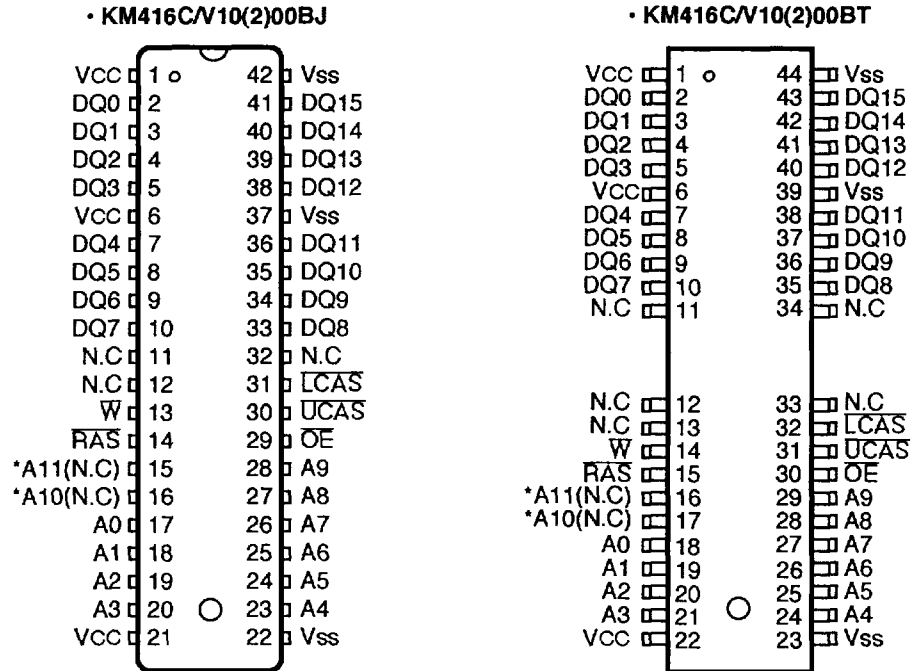
FUNCTIONAL BLOCK DIAGRAM



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SAMS061

PIN CONFIGURATION (Top Views)



* A10 and A11 are N.C for KM416C/V1200B (5V/3.3V, 1K Ref. product)

J : 400mil 42 SOJ
T : 400mil 50(44) TSOP II

Pin Name	Pin Function
A0 - A11	Address Inputs (4K Product)
A0 - A9	Address Inputs (1K Product)
DQ0 - 15	Data In/Out
Vss	Ground
RAS	Row Address Strobe
UCAS	Upper Column Address Strobe
LCAS	Lower Column Address Strobe
W	Read/Write Input
OE	Data Outputs Enable
VCC	Power (+5.0V)
	Power (+3.3V)
N.C	No Connection

ABSOLUTE MAXIMUM RATINGS *

Parameter	Symbol	Min	Max	Unit
Voltage on any pin relative to V _{SS}	V _{IN,VOUT}	-0.5	+4.6	V
Voltage on V _{CC} supply relative to V _{SS}	V _{CC}	-0.5	+4.6	V
Storage Temperature	T _{stg}	-55	+150	°C
Power Dissipation	P _D	1	1	W
Short Circuit Output Current	I _{OS}	50	50	mA

* Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS (Voltages referenced to V_{SS}, T_A= 0 to 70 °C)

Parameter	Symbol	3.0V	3.3V	3.6V	4.5V	5.0V	5.5V	Unit
Supply Voltage	V _{CC}	3.0	3.3	3.6	4.5	5.0	5.5	V
Ground	V _{SS}	0	0	0	0	0	0	V
Input High Voltage	V _{IH}	2.0	-	V _{CC} +0.3 ^{*1}	2.4	-	V _{CC} +1 ^{*1}	V
Input Low Voltage	V _{IL}	-0.3 ^{*2}	-	0.8	-1.0 ^{*2}	-	0.8	V

*1 : V_{CC}+1.3V/15ns(3.3V), V_{CC}+2.0V/20ns(5V), Pulse width is measured at V_{CC}.

*2 : -1.3V/15ns(3.3V), -2.0V/20ns(5V), Pulse width is measured at V_{SS}.

DC AND OPERATING CHARACTERISTICS

(Recommended operating conditions unless otherwise noted.)

Supply Voltage	Parameter	Symbol	Min	Max	Unit
3.3V	Input Leakage Current (Any input 0≤V _{IN} ≤V _{CC} +0.3V, all other pins not under test=0 volt.)	I _{I(L)}	-5	5	μA
	Output Leakage Current (Data out is disabled, 0V≤V _{OUT} ≤V _{CC})	I _{O(L)}	-5	5	μA
	Output High Voltage Level (I _{OH} =-2mA)	V _{OH}	2.4	-	V
	Output Low Voltage Level (I _{OL} =2mA)	V _{OL}	-	0.4	V
5V	Input Leakage Current (Any input 0≤V _{IN} ≤V _{CC} +0.5V, all other pins not under test=0 volt.)	I _{I(L)}	-5	5	μA
	Output Leakage Current (Data out is disabled, 0V≤V _{OUT} ≤V _{CC})	I _{O(L)}	-5	5	μA
	Output High Voltage Level (I _{OH} =-5mA)	V _{OH}	2.4	-	V
	Output Low Voltage Level (I _{OL} =4.2mA)	V _{OL}	-	0.4	V

DC AND OPERATING CHARACTERISTICS

(Recommended operating conditions unless otherwise noted.)

Symbol	Power	Supply	10V	15V	20V	25V	Unit
I _{cc1}	Don't care	-5	110	160	110	160	mA
		-6	100	150	100	150	mA
		-7	90	140	90	140	mA
I _{cc2}	Normal L	Don't care	2	2	2	2	mA
			1	1	1	1	mA
I _{cc3}	Don't care	-5	110	160	110	160	mA
		-6	100	150	100	150	mA
		-7	90	140	90	140	mA
I _{cc4}	Don't care	-5	100	100	100	100	mA
		-6	90	90	90	90	mA
		-7	80	80	80	80	mA
I _{cc5}	Normal L	Don't care	1	1	1	1	mA
			200	200	200	200	μA
I _{cc6}	Don't care	-5	110	160	110	160	mA
		-6	100	150	100	150	mA
		-7	90	140	90	140	mA
I _{cc7}	L	Don't care	400	300	450	350	μA
I _{cc8}	L	Don't care	200	200	250	250	μA

I_{cc1}* : Operating Current (\overline{RAS} , \overline{UCAS} , \overline{CAS} , Address cycling @t_{RC}=min.)

I_{cc2} : Standby Current ($\overline{RAS}=\overline{UCAS}=\overline{CAS}=\overline{W}=V_{IH}$)

I_{cc3}* : \overline{RAS} -Only Refresh Current ($\overline{UCAS}=\overline{CAS}=V_{IH}$, \overline{RAS} , Address cycling @t_{RC}=min.)

I_{cc4}* : Fast Page Mode Current ($\overline{RAS}=V_{IL}$, \overline{UCAS} or \overline{CAS} , Address cycling @t_{PC}=min.)

I_{cc5} : Standby Current ($\overline{RAS}=\overline{UCAS}=\overline{CAS}=\overline{W}=V_{CC}-0.2V$)

I_{cc6}* : \overline{CAS} -before- \overline{RAS} Refresh Current (\overline{RAS} , \overline{UCAS} or \overline{CAS} cycling @t_{RC}=min.)

I_{cc7} : Battery back-up current, Average power supply current, Battery back-up mode

Input high voltage(V_{IH})=V_{CC}-0.2V, Input low voltage(V_{IL})=0.2V, $\overline{UCAS}, \overline{CAS}=0.2V$,

Din = Don't care, T_{RC}= 31.25μs(4K/L-ver), 125μs(1K/L-ver), T_{RAS}=T_{RASmin}~300ns

I_{cc8} : Self Refresh Current

$\overline{RAS}=\overline{UCAS}=\overline{CAS}=V_{IL}$, $\overline{W}=\overline{OE}=A0 \sim A11 = V_{CC}-0.2V$ or 0.2V, --

DQ0 ~ DQ15= V_{CC}-0.2V, 0.2V or Open

* NOTE : I_{cc1}, I_{cc3}, I_{cc4} and I_{cc6} are dependent on output loading and cycle rates. Specified values are obtained with the output open. I_{cc} is specified as an average current. In I_{cc1}, I_{cc3}, and I_{cc6}, address can be changed maximum once while $\overline{RAS}=V_{IL}$. In I_{cc4}, address can be changed maximum once within one fast page mode cycle time, t_{PC}.

CAPACITANCE ($T_A=25^\circ\text{C}$, $V_{CC}=5\text{V}$ or 3.3V , $f=1\text{MHz}$)

Parameter	Symbol	Min	Max	Unit
Input capacitance [A0 - A11]	C_{IN1}	-	5	pF
Input capacitance [$\overline{\text{RAS}}$, $\overline{\text{UCAS}}$, $\overline{\text{LCAS}}$, $\overline{\text{W}}$, $\overline{\text{OE}}$]	C_{IN2}	-	7	pF
Output Capacitance [DQ0 - DQ15]	C_{DQ}	-	7	pF

AC CHARACTERISTICS ($0^\circ\text{C} \leq T_A \leq 70^\circ\text{C}$, See note 1, 2)

Test condition (5V device) : $V_{CC}=5.0\text{V} \pm 10\%$, $V_{IH}/V_{IL}=2.4/0.8\text{V}$, $V_{OH}/V_{OL}=2.4/0.4\text{V}$

Test condition (3.3V device) : $V_{CC}=3.3\text{V} \pm 0.3\text{V}$, $V_{IH}/V_{IL}=2.2/0.7\text{V}$, $V_{OH}/V_{OL}=2.0/0.8\text{V}$

Parameter	Symbol	Min	Typ	Max	Min	Max	Unit	Notes	
Random read or write cycle time	tRC	90		110		130	ns		
Read-modify-write cycle time	tRWC	133		155		185	ns		
Access time from $\overline{\text{RAS}}$	tRAC		50		60	70	ns	3,4,9	
Access time from $\overline{\text{CAS}}$	tCAC		15		15	20	ns	3,4	
Access time from column address	tAA		25		30	35	ns	3,9	
$\overline{\text{CAS}}$ to output in Low-Z	tCLZ	0		0		0	ns	3	
Output buffer turn-off delay	tOFF	0	13	0	15	0	20	ns	5
Transition time (rise and fall)	tT	3	50	3	50	3	50	ns	2
$\overline{\text{RAS}}$ precharge time	tRP	30		40		50	ns		
$\overline{\text{RAS}}$ pulse width	tRAS	50	10K	60	10K	70	10K	ns	
$\overline{\text{RAS}}$ hold time	tRSH	13		15		20	ns		
$\overline{\text{CAS}}$ hold time	tCSH	50		60		70	ns		
$\overline{\text{CAS}}$ pulse width	tCAS	13	10K	15	10K	20	10K	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ delay time	tRCD	20	37	20	45	20	50	ns	4
$\overline{\text{RAS}}$ to column address delay time	tRAD	15	25	15	30	15	35	ns	9
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ precharge time	tCRP	5		5		5	ns		
Row address set-up time	tASR	0		0		0	ns		
Row address hold time	tRAH	10		10		10	ns		
Column address set-up time	tASC	0		0		0	ns	10	
Column address hold time	tCAH	10		10		15	ns	10	
Column address to $\overline{\text{RAS}}$ lead time	tRAL	25		30		35	ns		
Read command set-up time	tRCS	0		0		0	ns		
Read command hold time referenced to $\overline{\text{CAS}}$	tRCH	0		0		0	ns	7	
Read command hold time referenced to $\overline{\text{RAS}}$	tRRH	0		0		0	ns	7	
Write command hold time	tWCH	10		10		15	ns		
Write command pulse width	tWP	10		10		15	ns		
Write command to $\overline{\text{RAS}}$ lead time	tRWL	15		15		20	ns		
Write command to $\overline{\text{CAS}}$ lead time	tCWL	13		15		20	ns	13	

AC CHARACTERISTICS ($0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, See note 2)

Test condition (5V device) : $V_{CC}=5.0\text{V} \pm 10\%$, $V_{IH}/V_{IL}=2.4/0.8\text{V}$, $V_{OH}/V_{OL}=2.4/0.4\text{V}$

Test condition (3.3V device) : $V_{CC}=3.3\text{V} \pm 0.3\text{V}$, $V_{IH}/V_{IL}=2.2/0.7\text{V}$, $V_{OH}/V_{OL}=2.0/0.8\text{V}$

Symbol	Unit	Notes
Data set-up time	tDS	0 0 0 ns 8, 16
Data hold time	tDH	10 10 15 ns 8, 16
Refresh period (1K, Normal)	tREF	16 16 16 ms
Refresh period (4K, Normal)	tREF	64 64 64 ms
Refresh period (L-ver)	tREF	128 128 128 ms
Write command set-up time	tWCS	0 0 0 ns 6
CAS to \bar{W} delay time	tCWD	36 40 50 ns 6, 12
RAS to \bar{W} delay time	tRWD	73 85 95 ns 6
Column address to \bar{W} delay time	tAWD	48 55 60 ns 6
CAS precharge to \bar{W} delay time	tCPWD	53 60 65 ns 6
CAS set-up time (CAS-before-RAS refresh)	tCSR	5 5 5 ns 14
CAS hold time (CAS-before-RAS refresh)	tCHR	10 10 15 ns 15
RAS to CAS precharge time	tRPC	5 5 5 ns
CAS precharge time (C-B-R counter test cycle)	tCPT	20 20 25 ns
Access time from CAS precharge	tCPA	30 35 40 ns 3
Fast Page mode cycle time	tPC	35 40 45 ns
Fast Page mode read-modify-write cycle time	tPRWC	76 80 95 ns
CAS precharge time (Fast page cycle)	tCP	10 10 10 ns 11
RAS pulse width (Fast page cycle)	tRASP	50 200K 60 200K 70 200K ns
RAS hold time from CAS precharge	tRHCP	30 35 40 ns
OE access time	tOEA	13 15 20 ns 3
OE to data delay	tOED	13 15 20 ns
Output buffer turn off delay time from OE	tOEZ	0 13 0 15 0 20 ns
OE command hold time	tOEH	13 15 20 ns
RAS pulse width (C-B-R self refresh)	tRASS	100 100 100 us 17
RAS precharge time (C-B-R self refresh)	tRPS	90 110 130 ns 17
CAS hold time (C-B-R self refresh)	tCHS	-50 -50 -50 ns 17

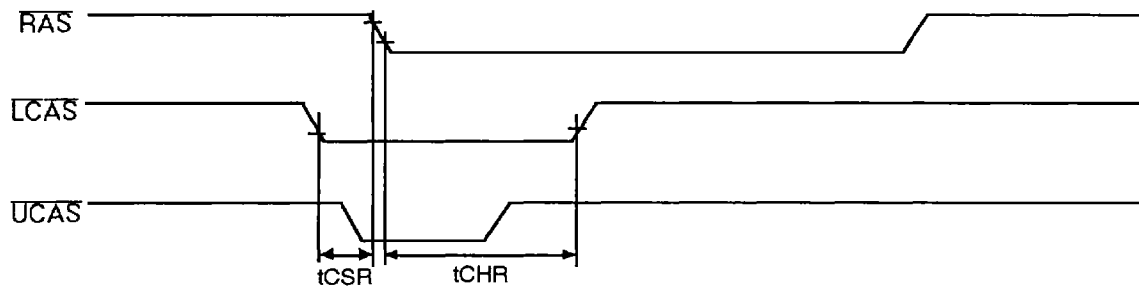
NOTES

1. An initial pause of 200us is required after power-up followed by any 8 ROR or CBR refresh cycles before proper device operation is achieved.
2. Input voltage levels are V_{IH} and V_{IL} , and $V_{IH(min)}$ and $V_{IL(max)}$ are reference levels for measuring timing of input signals. Transition times are measured between $V_{IH(min)}$ and $V_{IL(max)}$ and are assumed to be 5ns for all inputs.
3. Measured with a load equivalent to 2 TTL (5V device)/ 1 TTL(3.3V device) loads and 100pF.
4. Operation within the $t_{RCD(max)}$ limit insures that $t_{RAC(max)}$ can be met. $t_{RCD(max)}$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{RCD(max)}$ limit, then access time is controlled exclusively by t_{CAC} .
5. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL} .
6. t_{WCS} , t_{RWD} , t_{CWD} , t_{AWD} and t_{CPWD} are non restrictive operating parameters. They are included in the data sheet as electric characteristics only. If $t_{WCS} \geq t_{WCS(min)}$, the cycle is an early write cycle and the data output will remain high impedance for the duration of the cycle. If $t_{CWD} \geq t_{CWD(min)}$, $t_{RWD} \geq t_{RWD(min)}$, $t_{AWD} \geq t_{AWD(min)}$ and $t_{CPWD} \geq t_{CPWD(min)}$, then the cycle is a read-modify-write cycle and the data output will contain the data read from the selected address. If neither of the above conditions is satisfied, the condition of the data out is indeterminate.
7. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
8. These parameters are referenced to the \overline{CAS} leading edge in early write cycles and to the \overline{W} leading edge in read-modify-write cycles.
9. Operation within the $t_{RAD(max)}$ limit insures that $t_{RAC(max)}$ can be met. $t_{RAD(max)}$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{RAD(max)}$ limit, then access time is controlled by t_{AA} .

KM416C/V10(2)00B/B-L Truth Table

H	X	X	X	X	Hi-Z	Hi-Z	Standby
L	H	H	X	X	Hi-Z	Hi-Z	Refresh
L	L	H	H	L	DQ-OUT	Hi-Z	Byte Read
L	H	L	H	L	Hi-Z	DQ-OUT	Byte Read
L	L	L	H	L	DQ-OUT	DQ-OUT	Word Read
L	L	H	L	H	DQ-IN	-	Byte Write
L	H	L	L	H	-	DQ-IN	Byte Write
L	L	L	L	H	DQ-IN	DQ-IN	Word Write
L	L	L	H	H	Hi-Z	Hi-Z	-

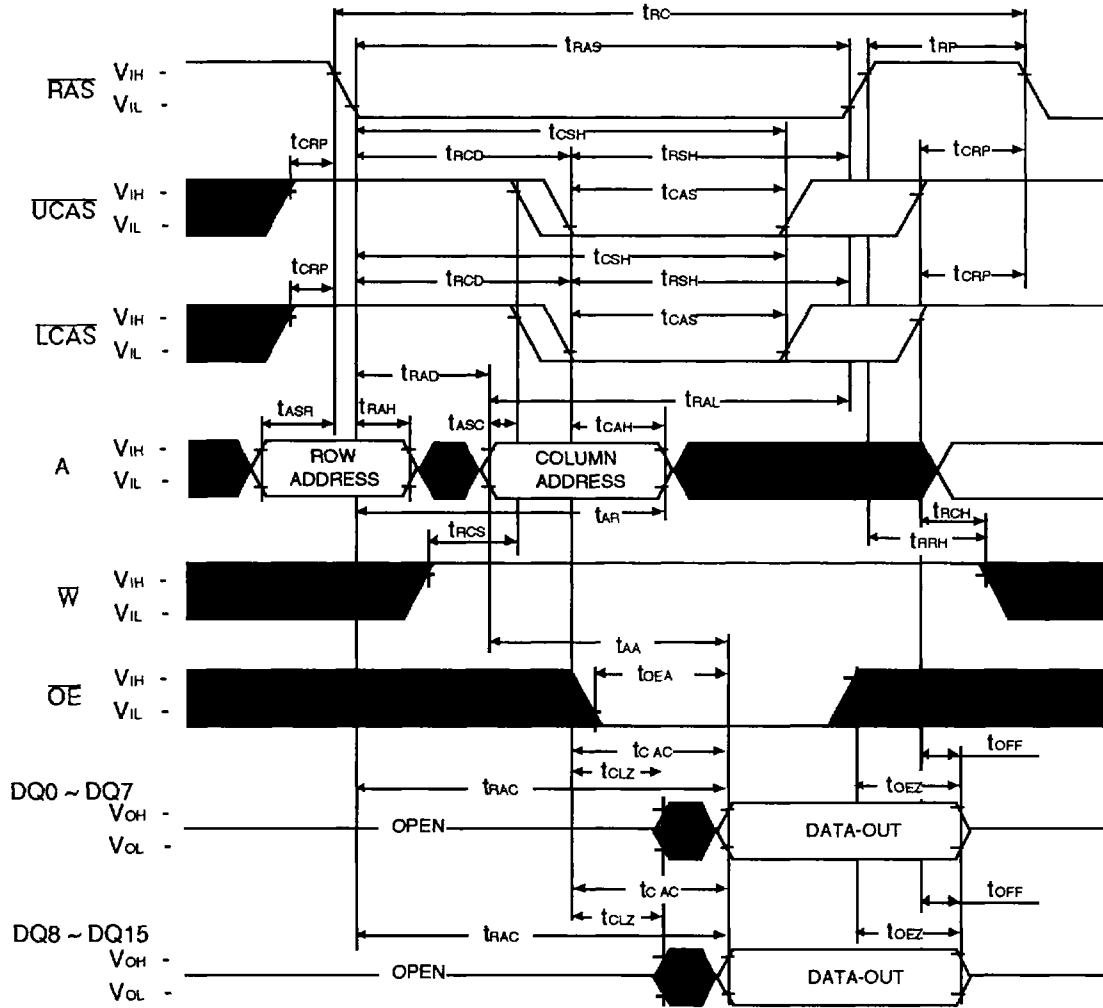
- 10. tASC, tCAH are referenced to the earlier $\overline{\text{CAS}}$ falling edge.
- 11. tCP is specified from the last $\overline{\text{CAS}}$ rising edge in the previous cycle to the first $\overline{\text{CAS}}$ falling edge in the next cycle.
- 12. tCWD is referenced to the later $\overline{\text{CAS}}$ falling edge at word read-modify-write cycle.
- 13. tCWL is specified from $\overline{\text{W}}$ falling edge to the earlier $\overline{\text{CAS}}$ rising edge.
- 14. tCSR is referenced to earlier $\overline{\text{CAS}}$ falling low before $\overline{\text{RAS}}$ transition low.
- 15. tCHR is referenced to the later $\overline{\text{CAS}}$ rising high after $\overline{\text{RAS}}$ transition low.



- 16. tDS, tDH is independently specified for lower byte $D_{IN}(0\sim7)$, upper byte $D_{IN}(8\sim15)$.
- 17. 4096(4K Ref.)/21024(1K Ref.)of burst refresh must be executed within 16ms before and after self-refresh in order to meet refresh specification (L-version).

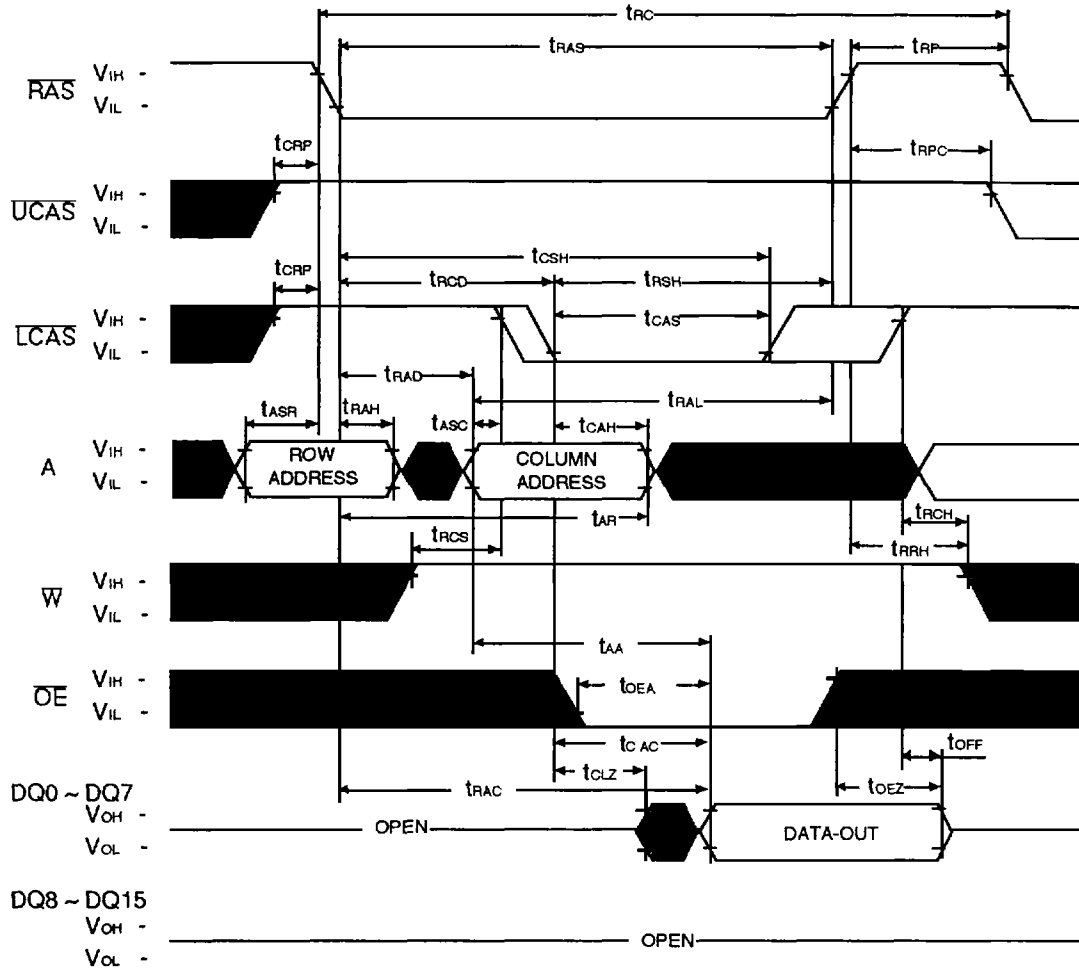
TIMING DIAGRAM
WORD READ CYCLE

NOTE : D_{IN} = OPEN



TIMING DIAGRAM
LOWER BYTE READ CYCLE

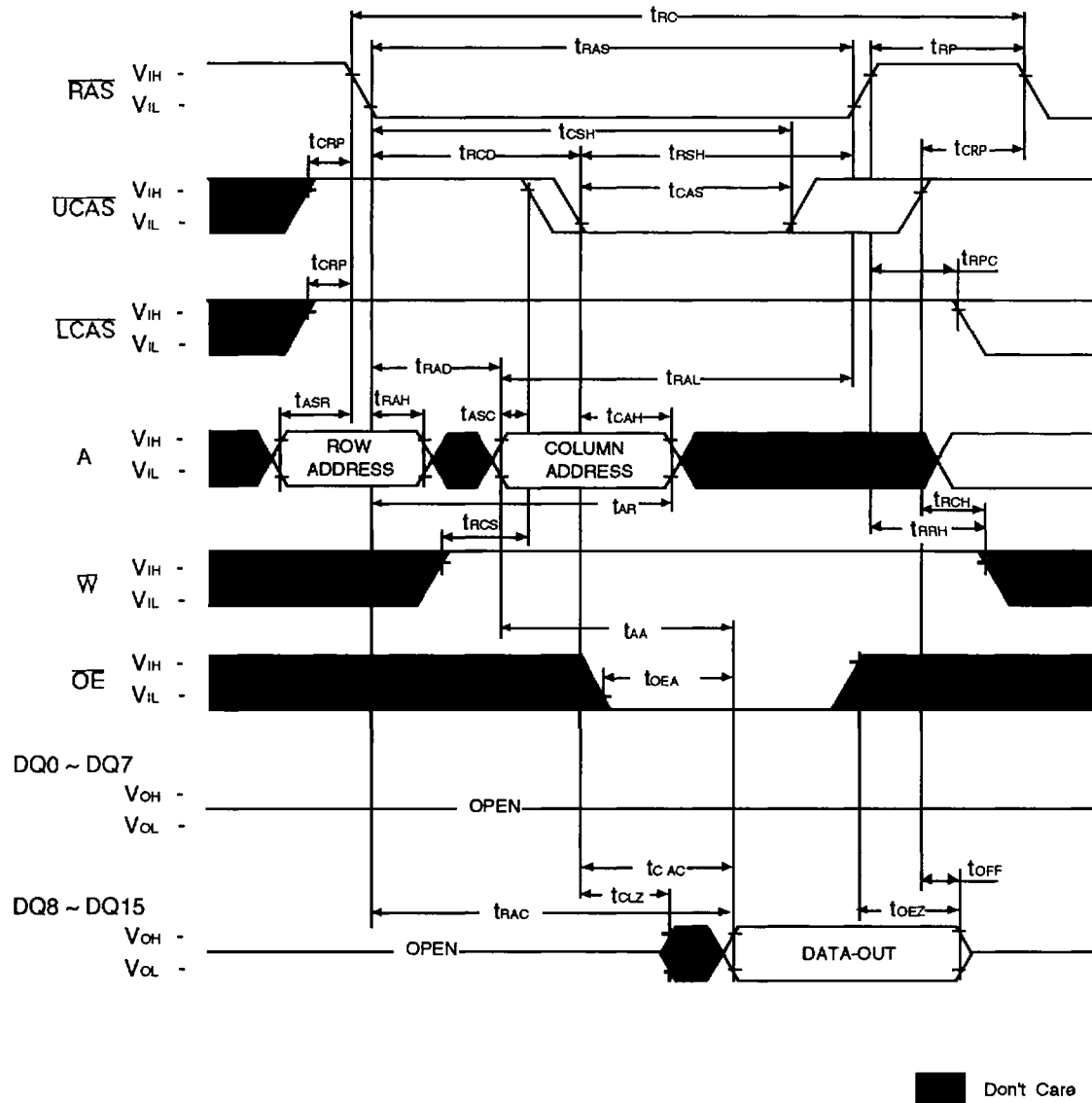
NOTE : $D_{IN} = OPEN$



■ Don't Care

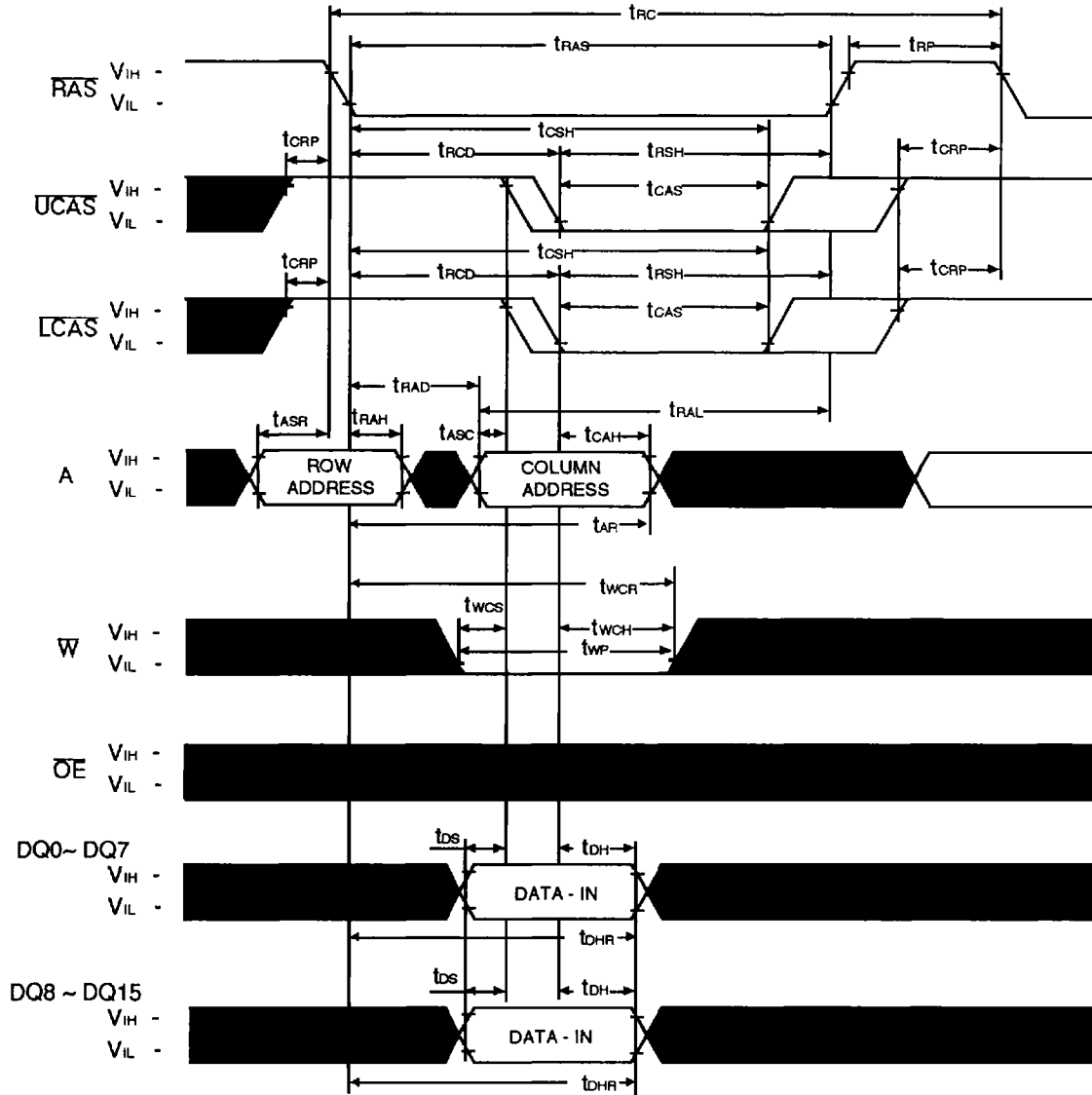
TIMING DIAGRAM
UPPER BYTE READ CYCLE

NOTE : D_{IN} = OPEN



WORD WRITE CYCLE (EARLY WRITE)

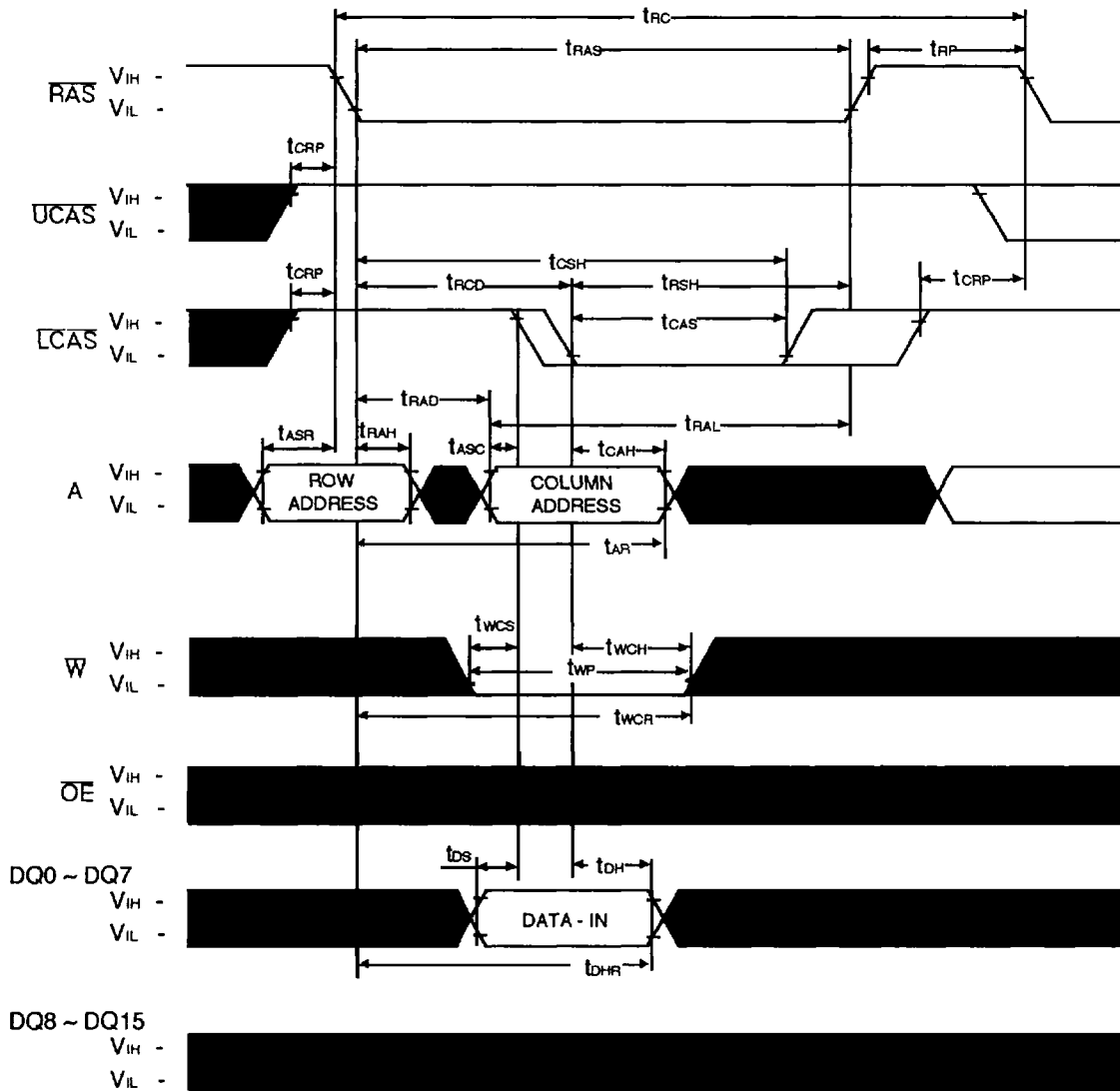
NOTE : $D_{out} = OPEN$



■ Don't Care

LOWER BYTE WRITE CYCLE (EARLY WRITE)

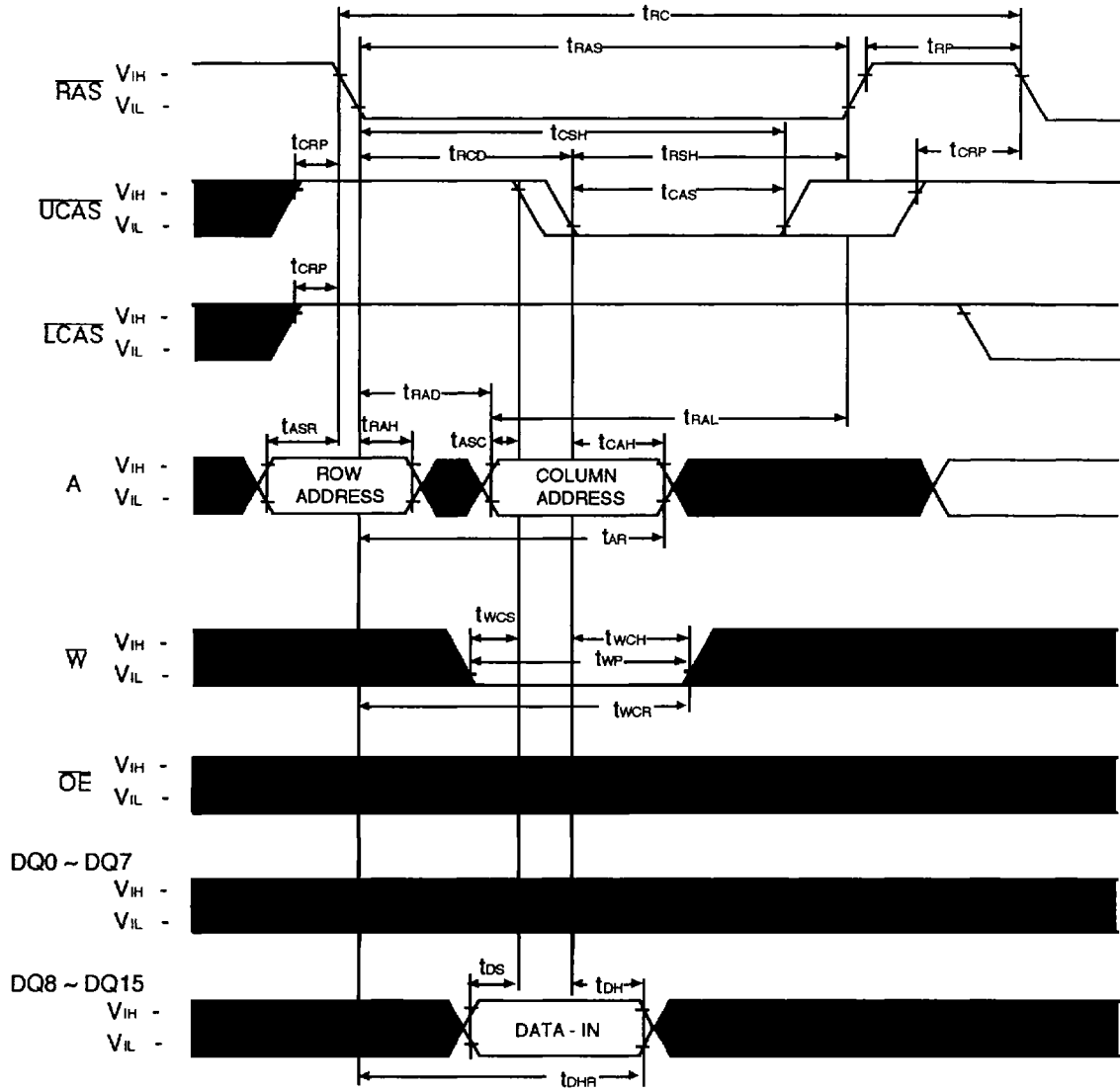
NOTE : D_{OUT} = OPEN



■ Don't Care

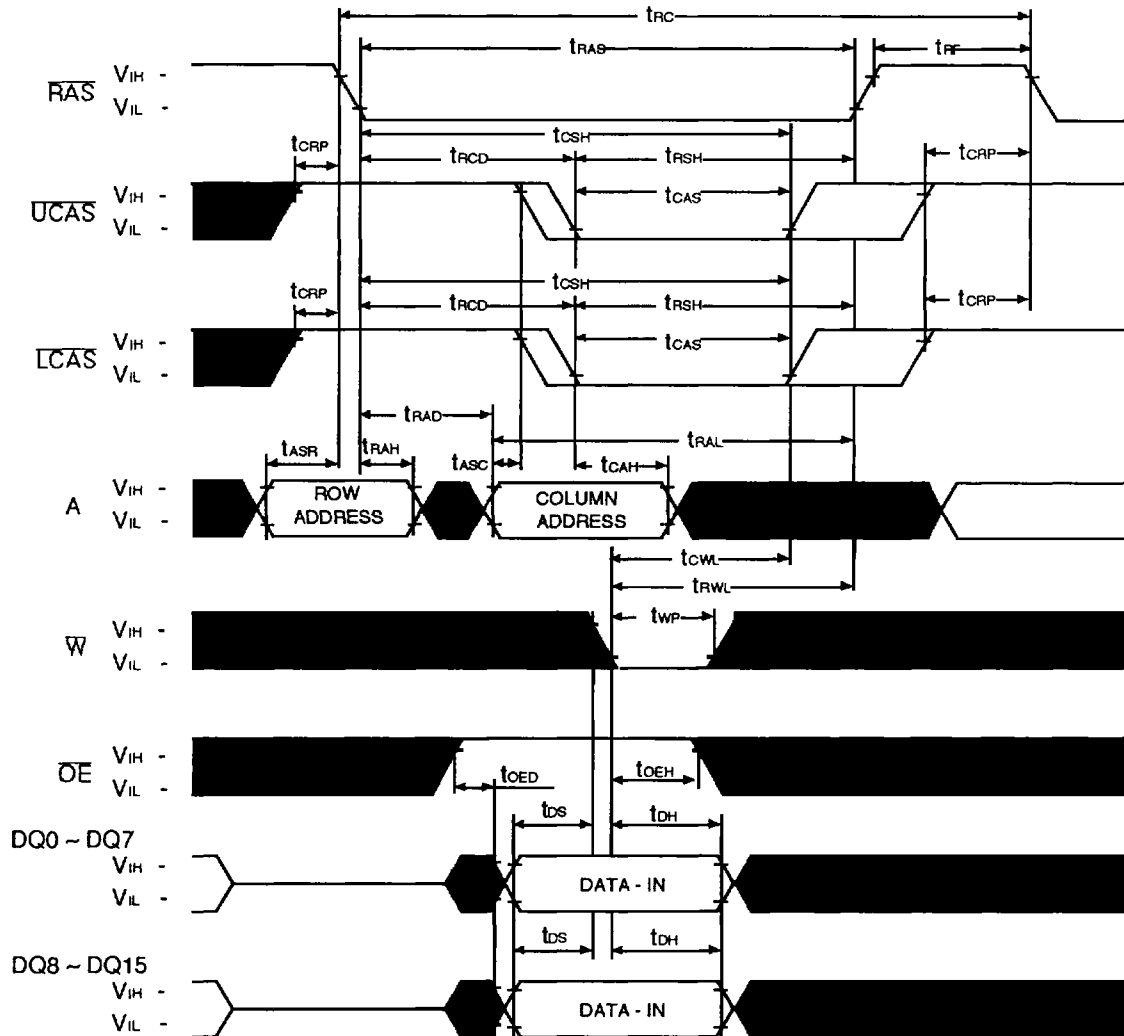
UPPER BYTE WRITE CYCLE (EARLY WRITE)

NOTE : D_{OUT} = OPEN



WORD WRITE CYCLE (OE CONTROLLED WRITE)

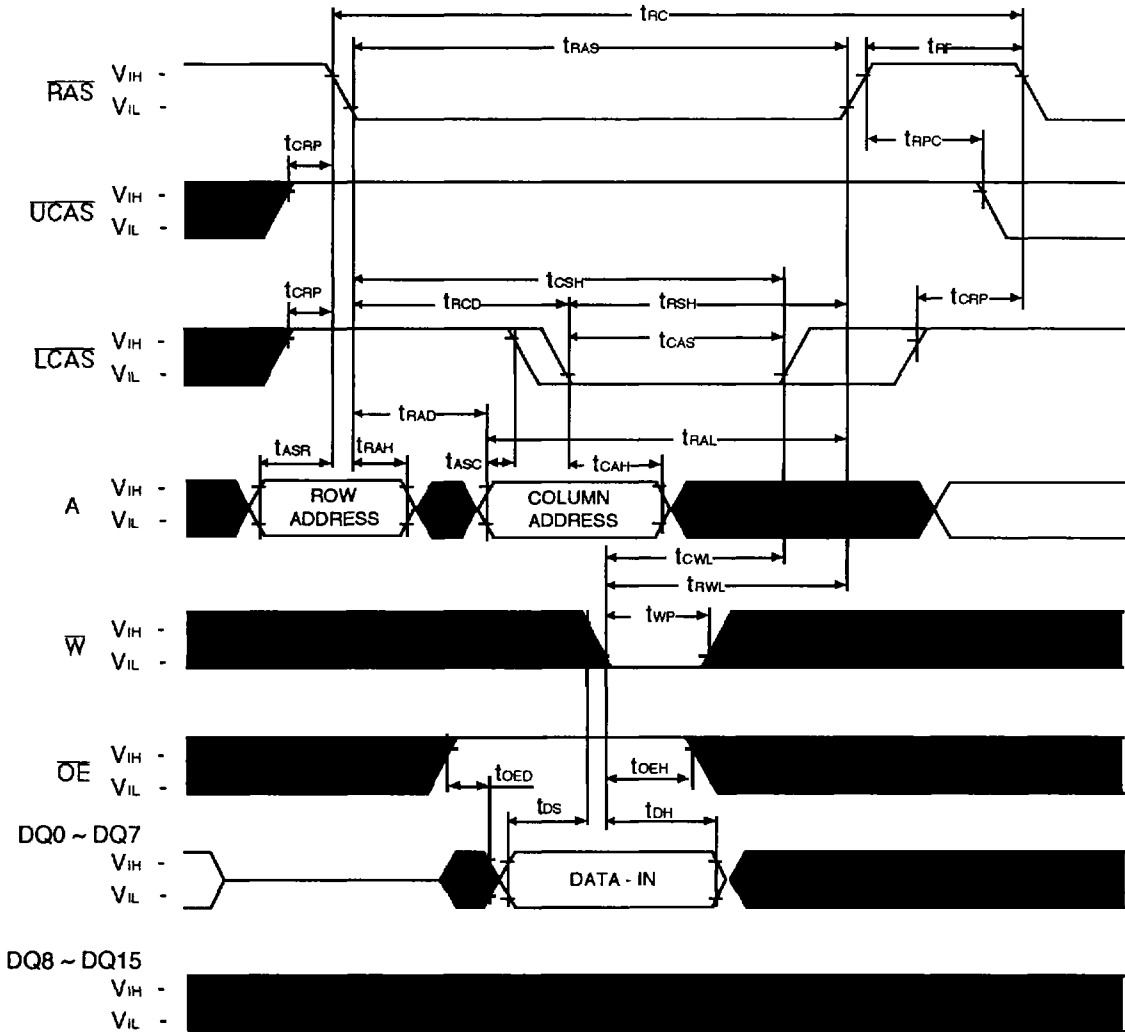
NOTE : D_{OUT} = OPEN



■ Don't Care

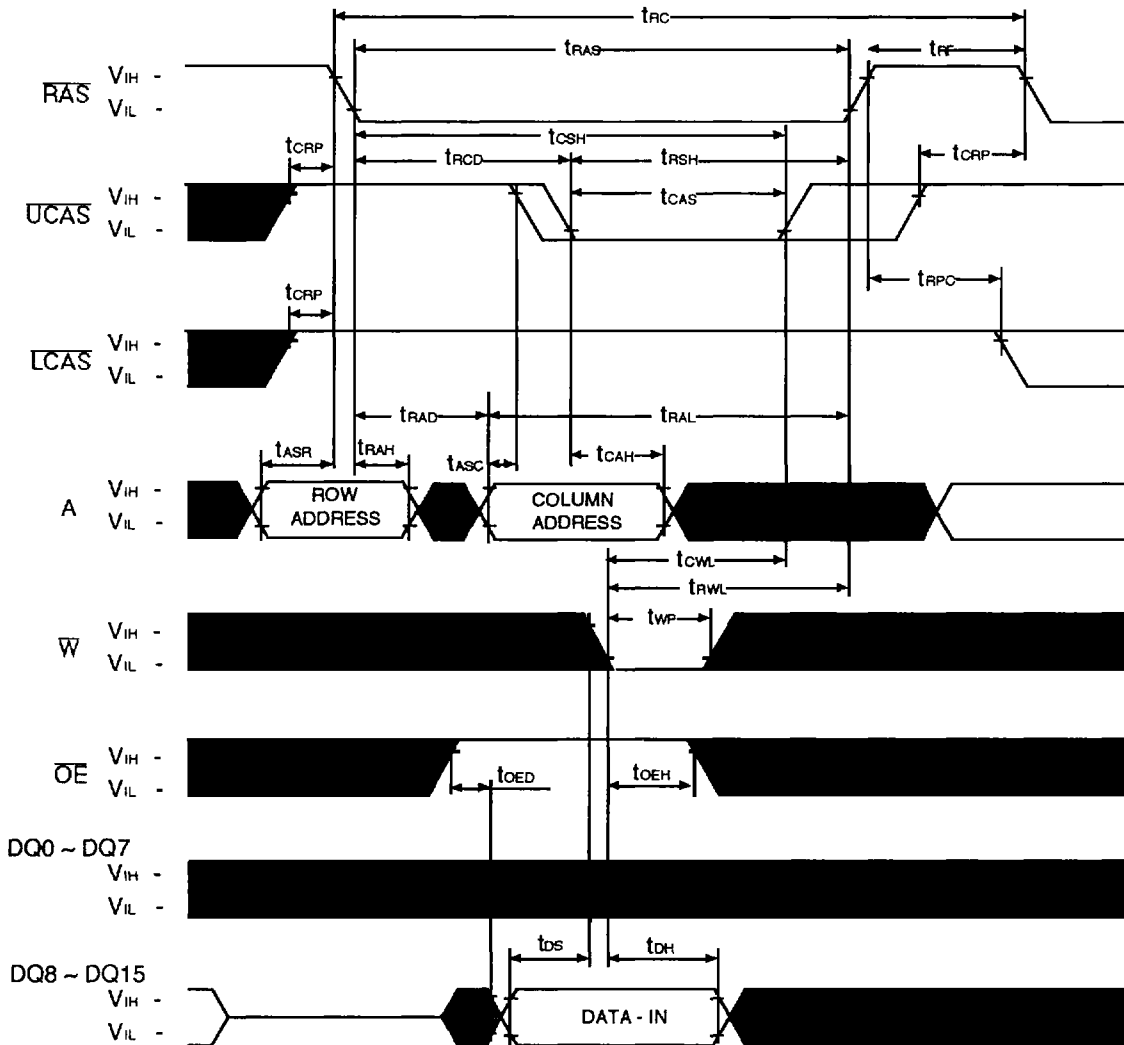
LOWER BYTE WRITE CYCLE (OE CONTROLLED WRITE)

NOTE : D_{OUT} = OPEN



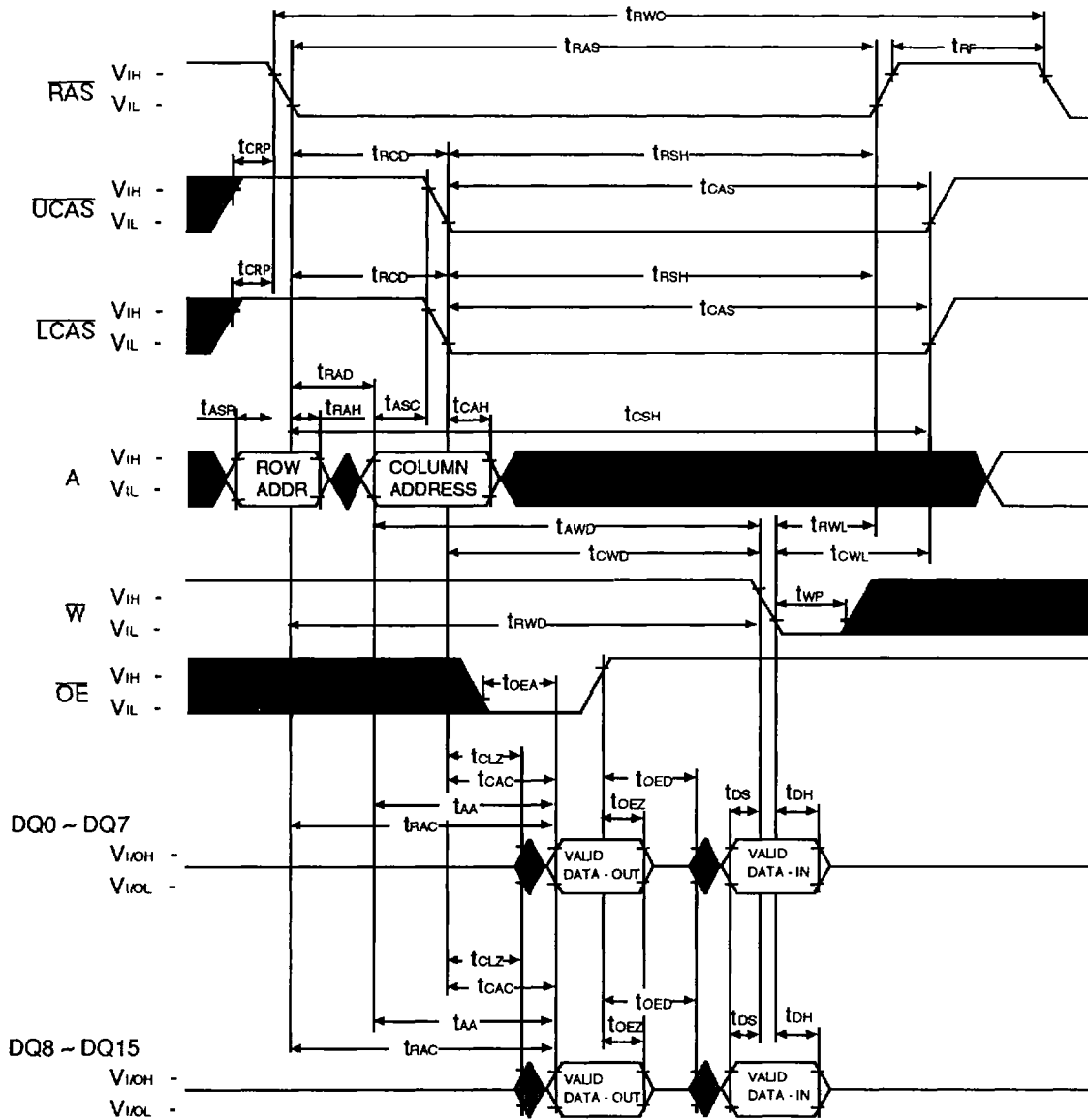
UPPER BYTE WRITE CYCLE (OE CONTROLLED WRITE)

NOTE : D_{OUT} = OPEN



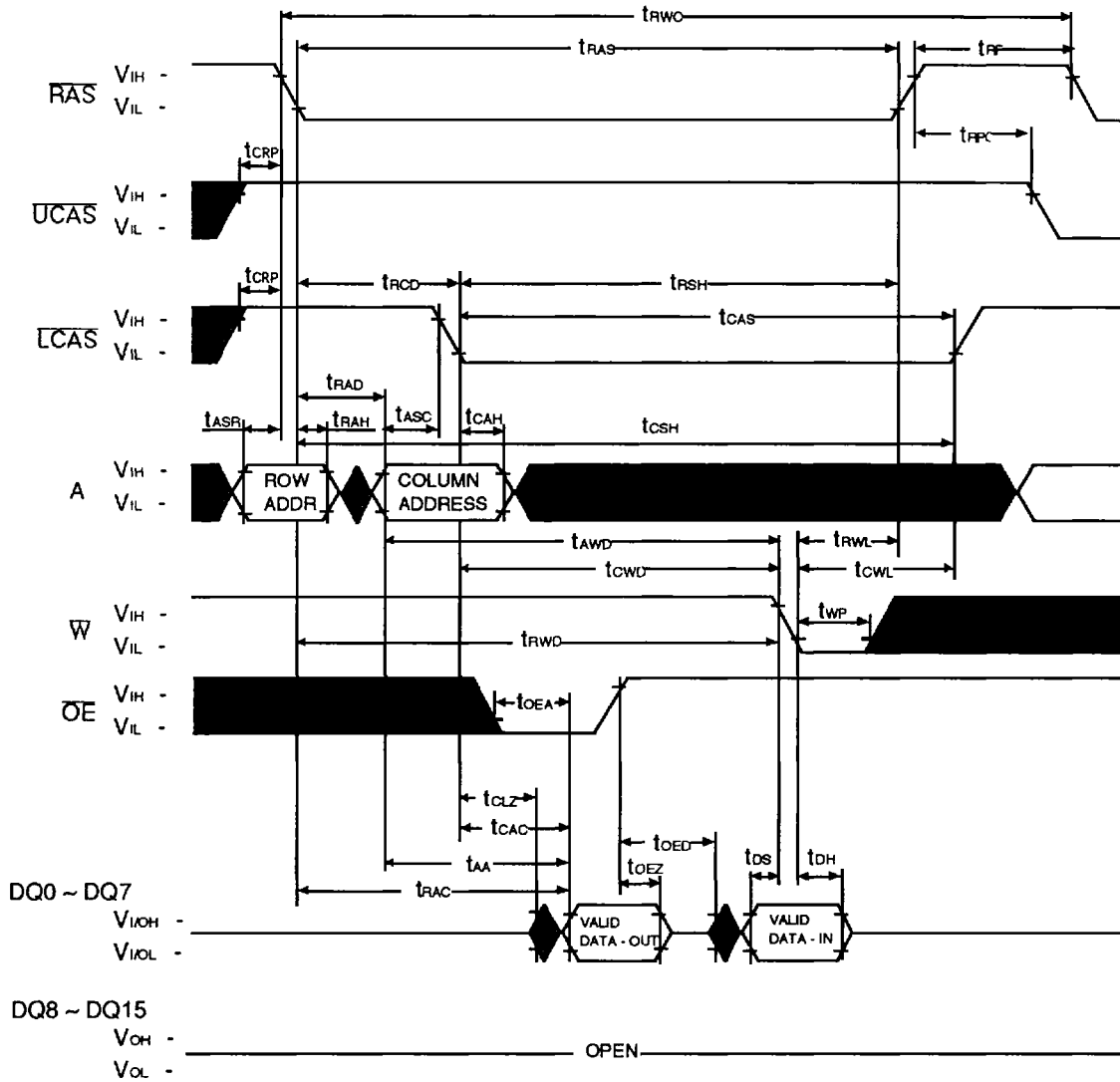
■ Don't Care

WORD READ - MODIFY - WRITE CYCLE

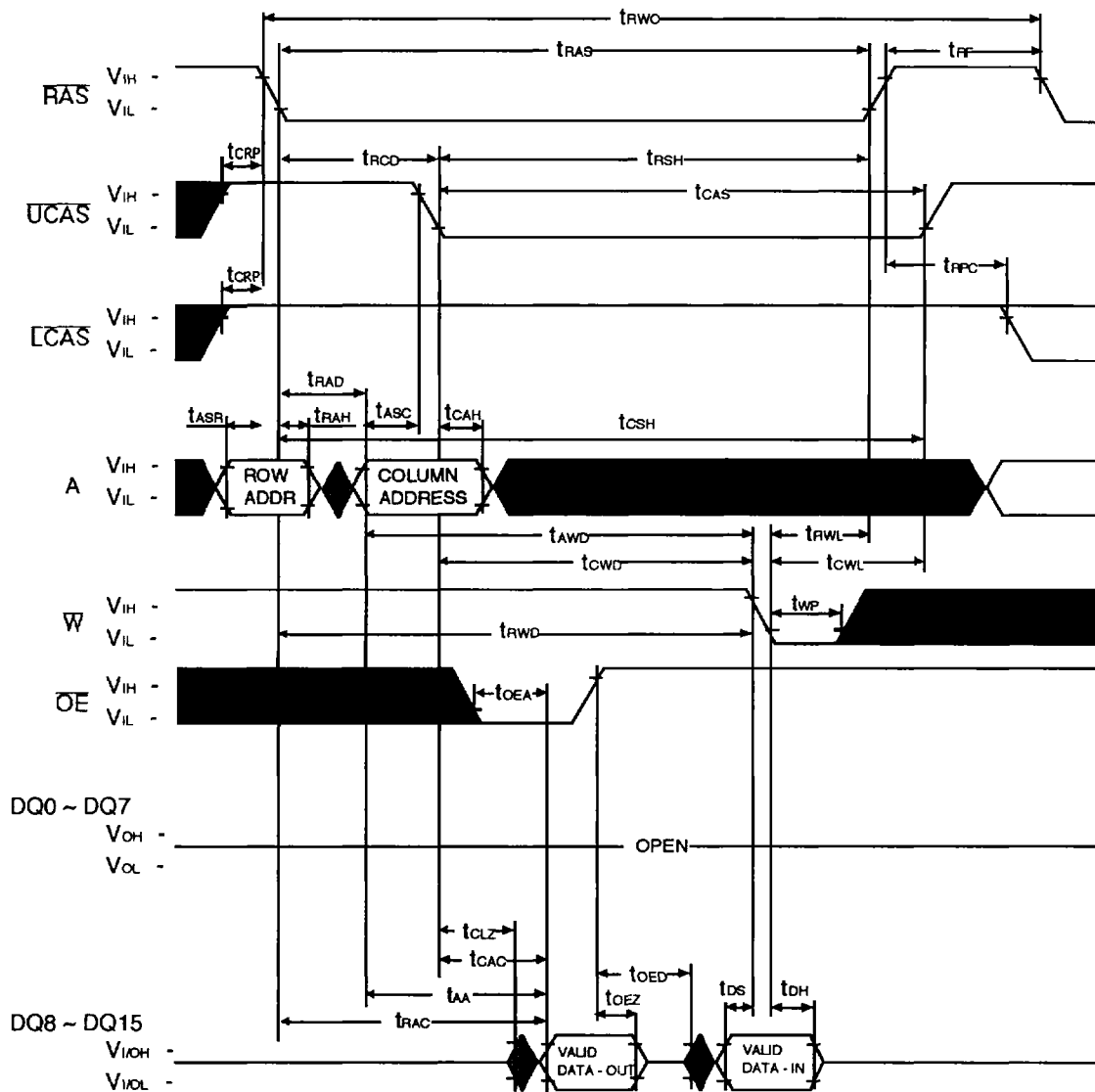


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LOWER-BYTE READ - MODIFY - WRITE CYCLE

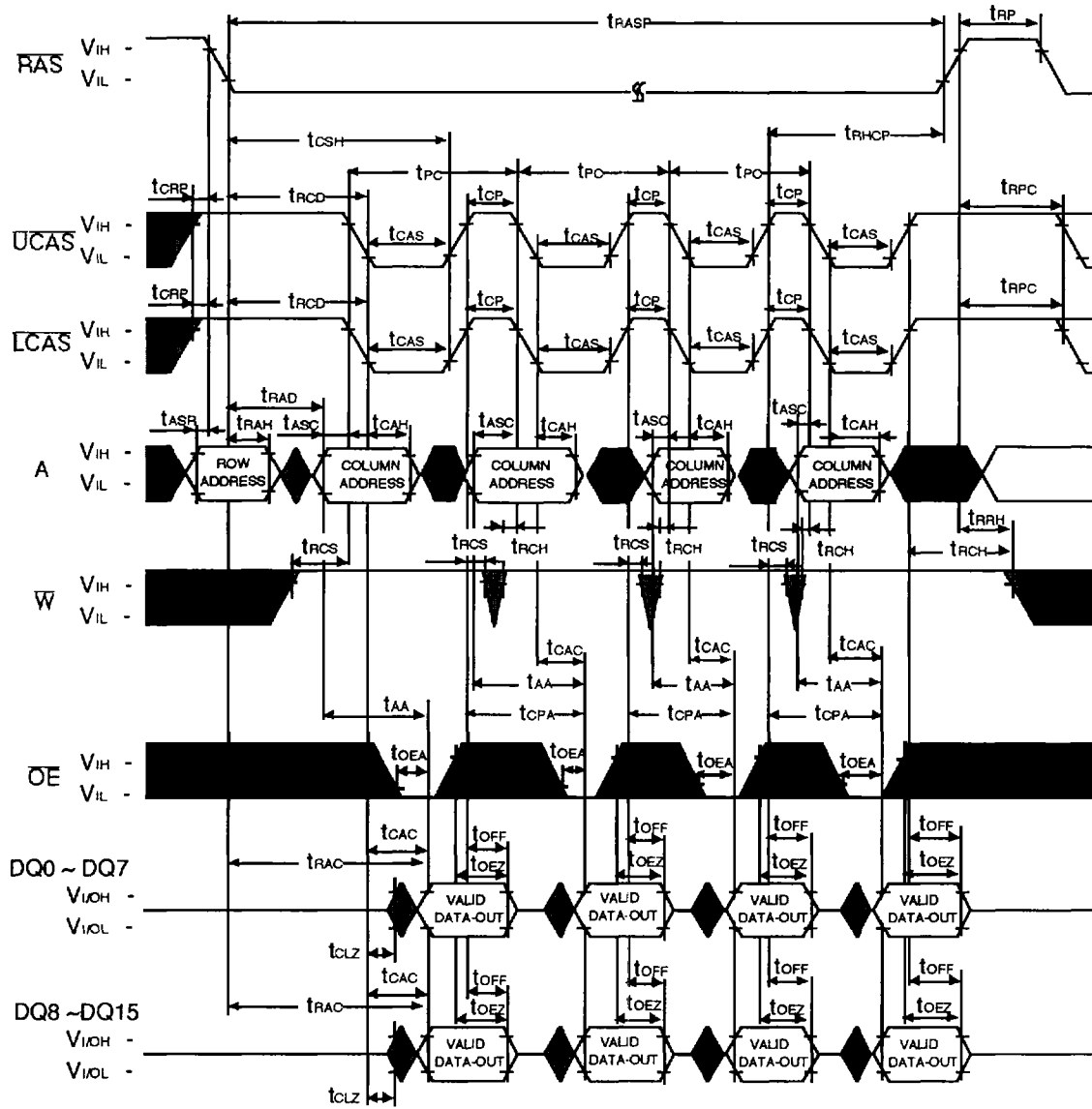


UPPER-BYTE READ - MODIFY - WRITE CYCLE



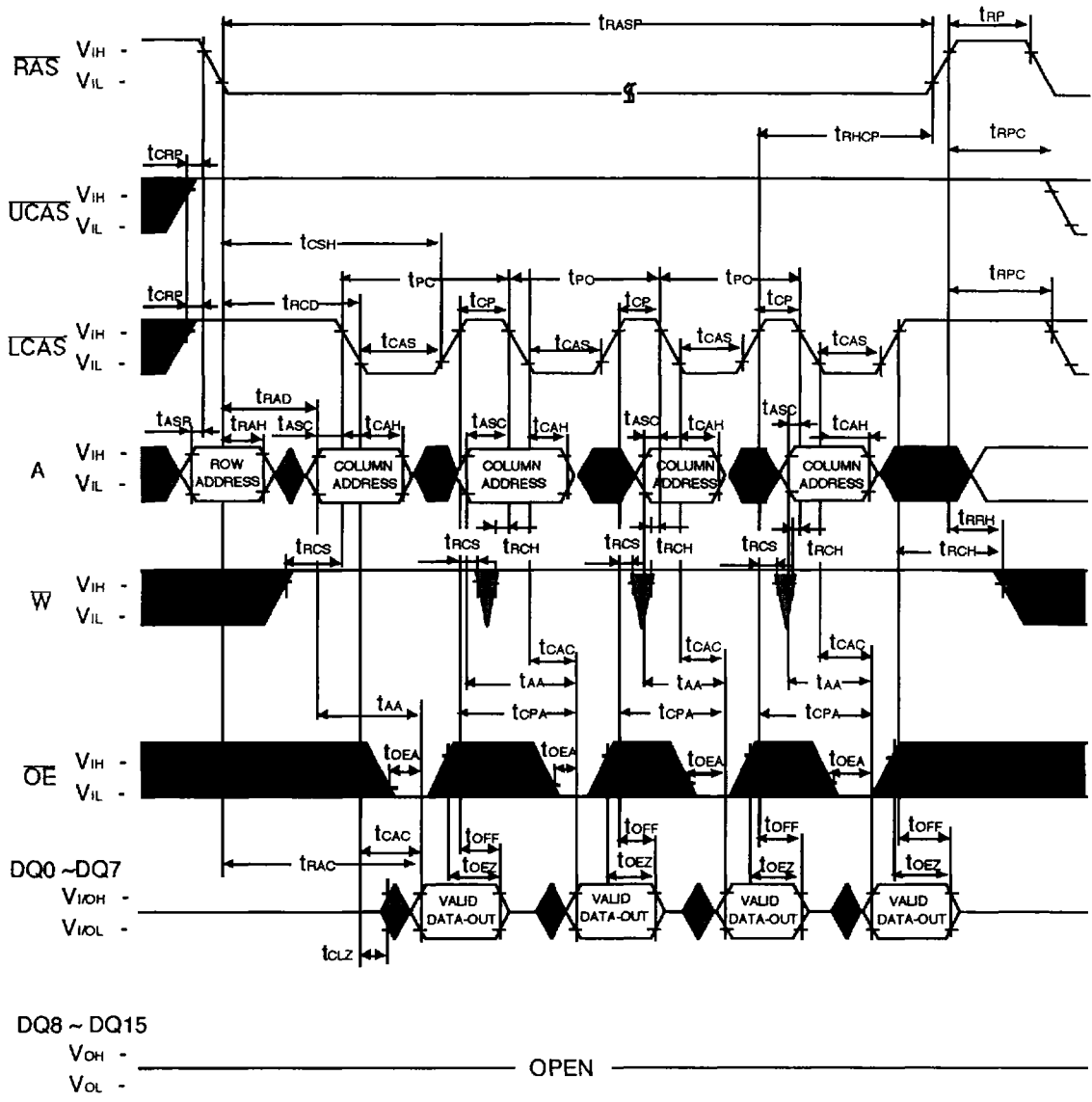
■ Don't Care

FAST PAGE MODE WORD READ CYCLE



■ Don't Care

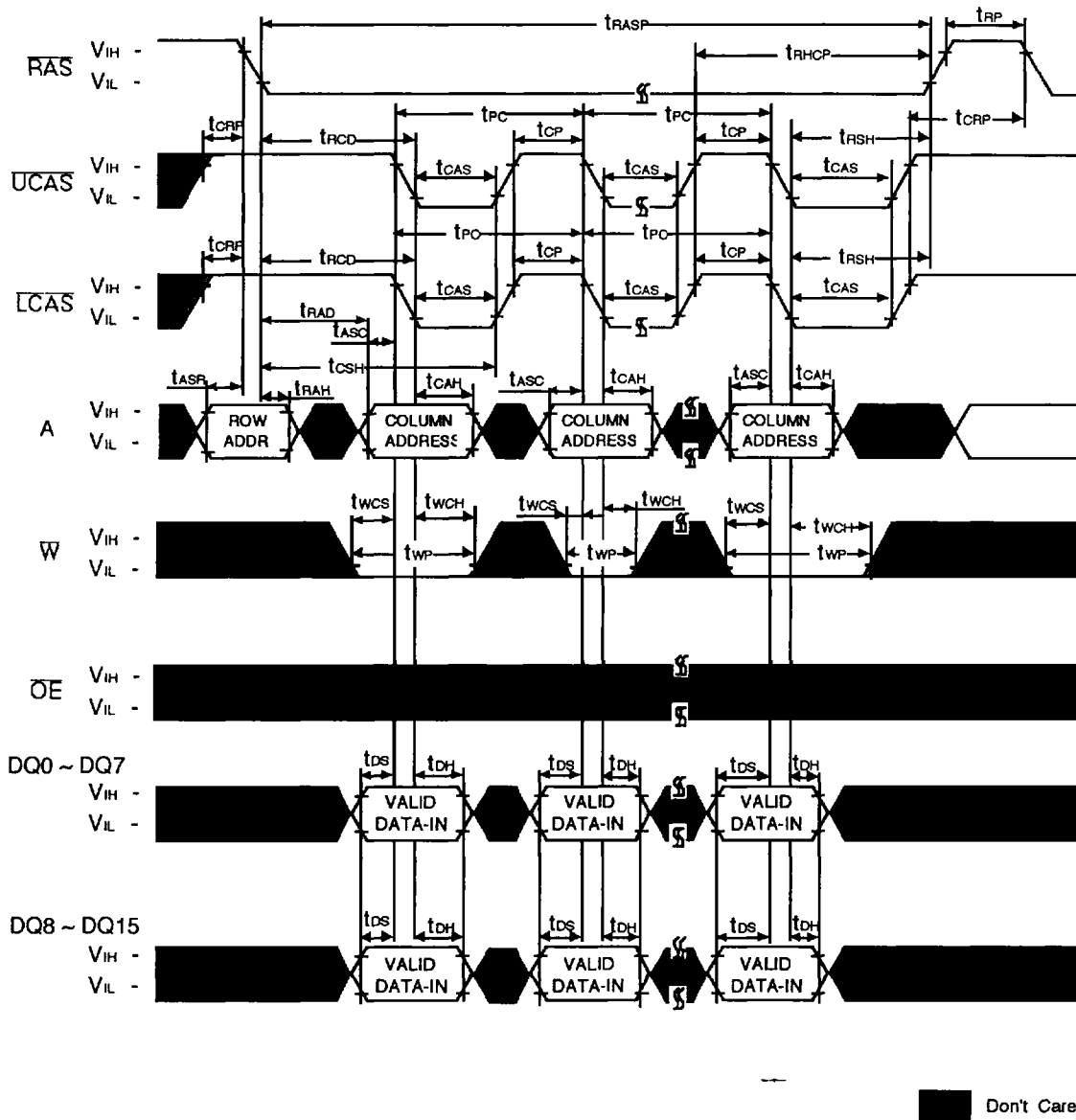
FAST PAGE MODE LOWER BYTE READ CYCLE



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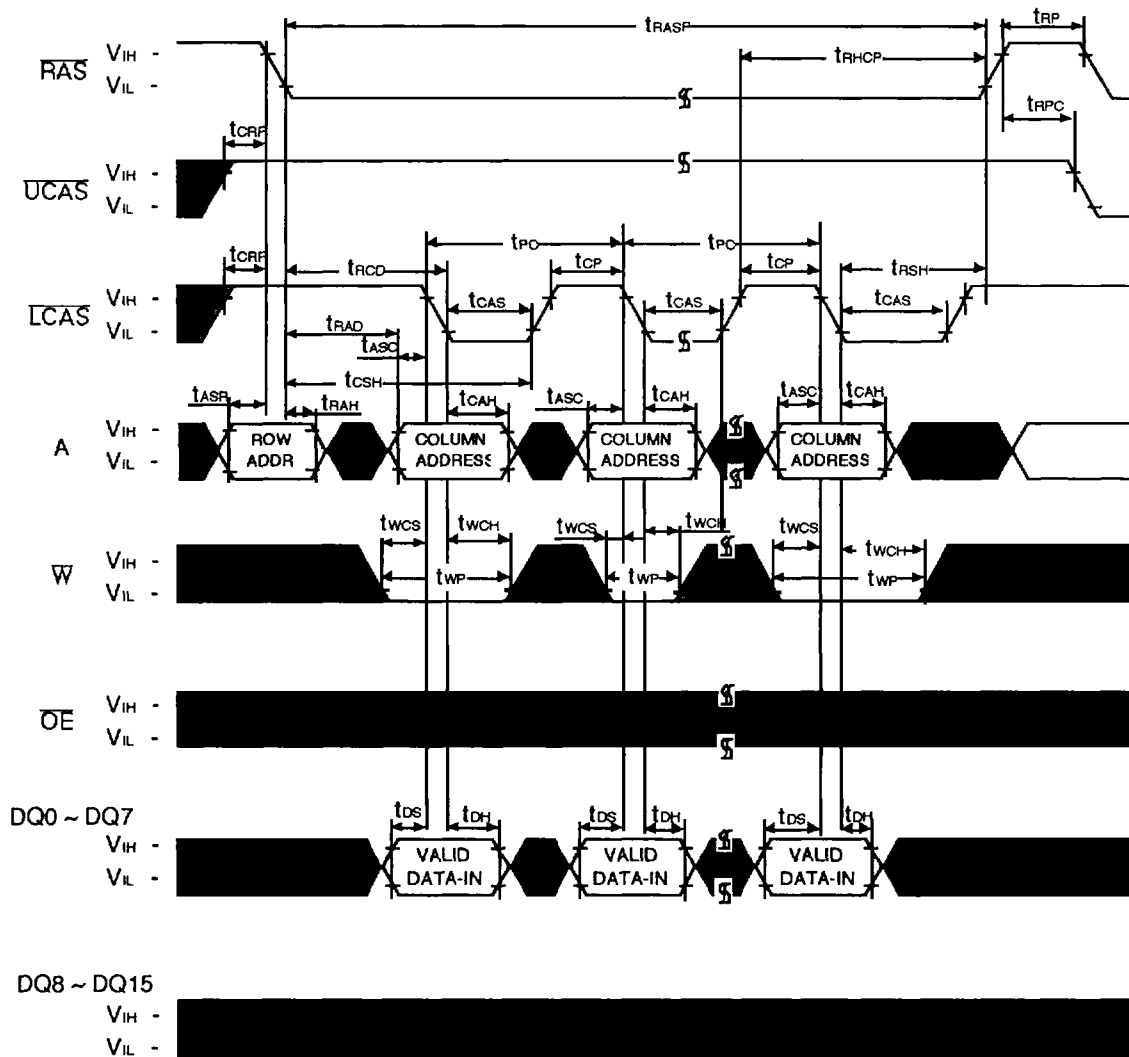
FAST PAGE MODE WORD WRITE CYCLE (EARLY WRITE)

NOTE : D_{OUT} = Open



FAST PAGE MODE LOWER BYTE WRITE CYCLE (EARLY WRITE)

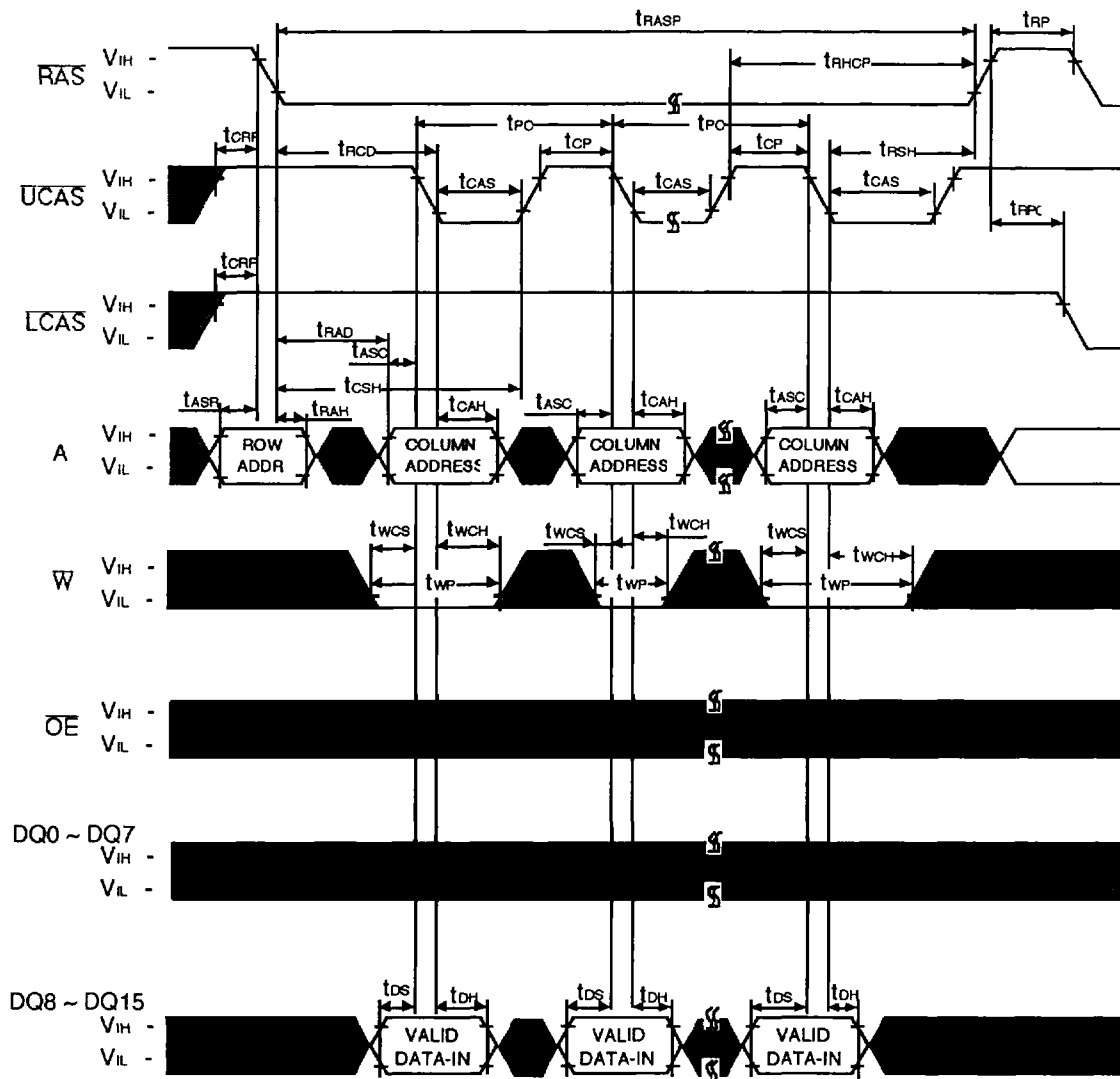
NOTE : Dout = Open



■ Don't Care

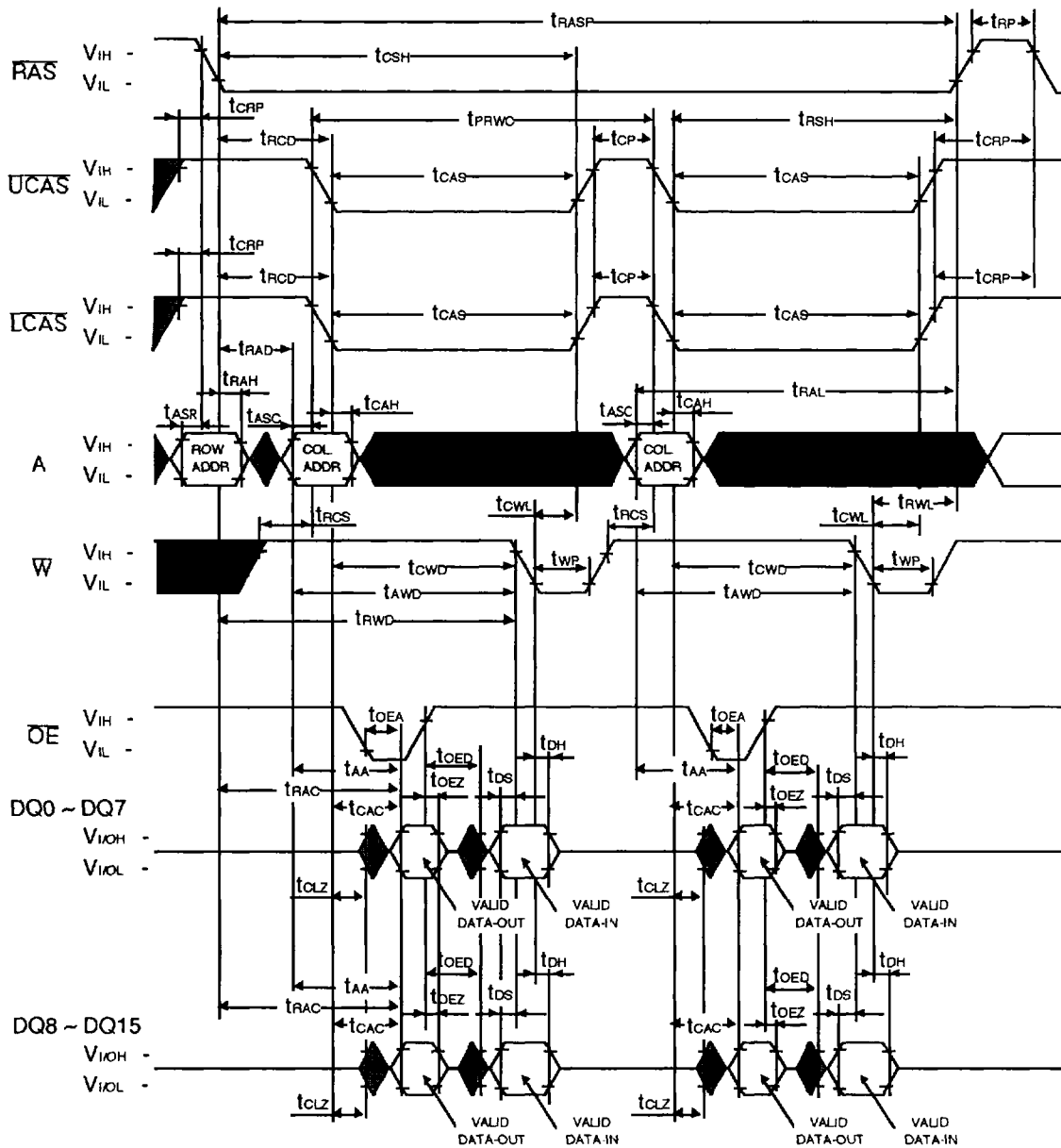
FAST PAGE MODE UPPER BYTE WRITE CYCLE (EARLY WRITE)

NOTE : D_{OUT} = Open



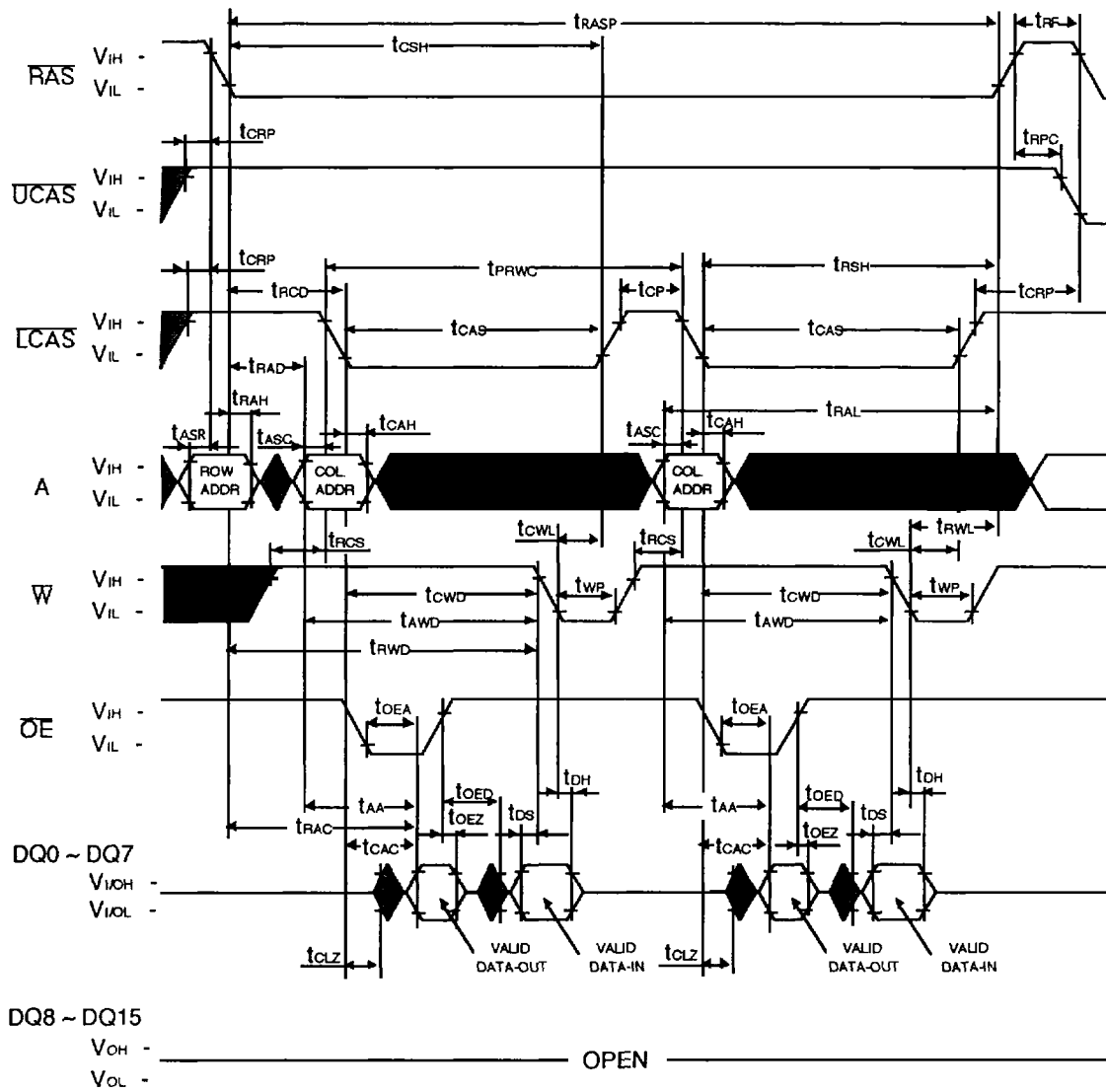
■ Don't Care

FAST PAGE MODE WORD READ-MODIFY-WRITE CYCLE

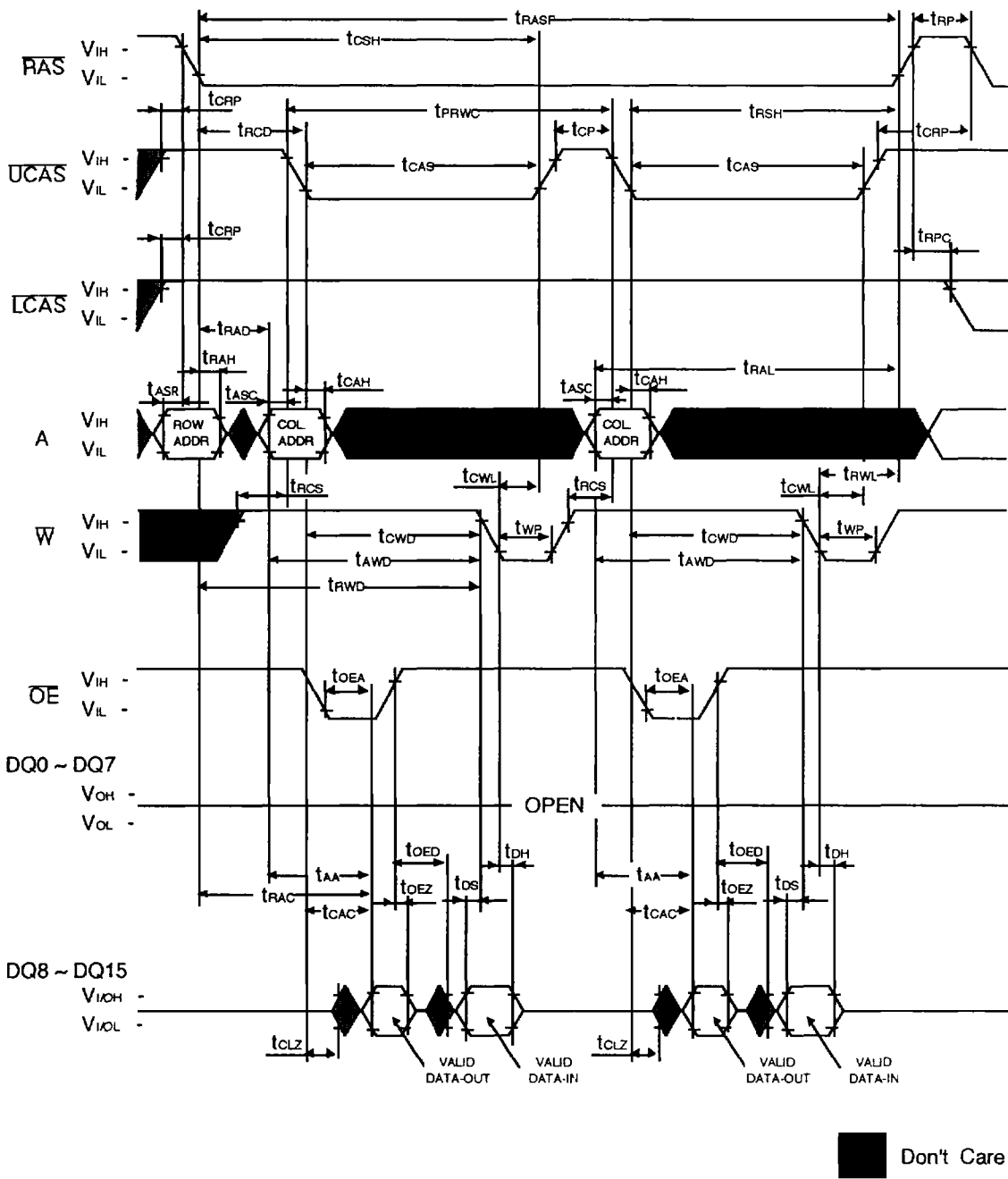


■ Don't Care

FAST PAGE MODE LOWER-BYTE-READ-MODIFY-WRITE CYCLE

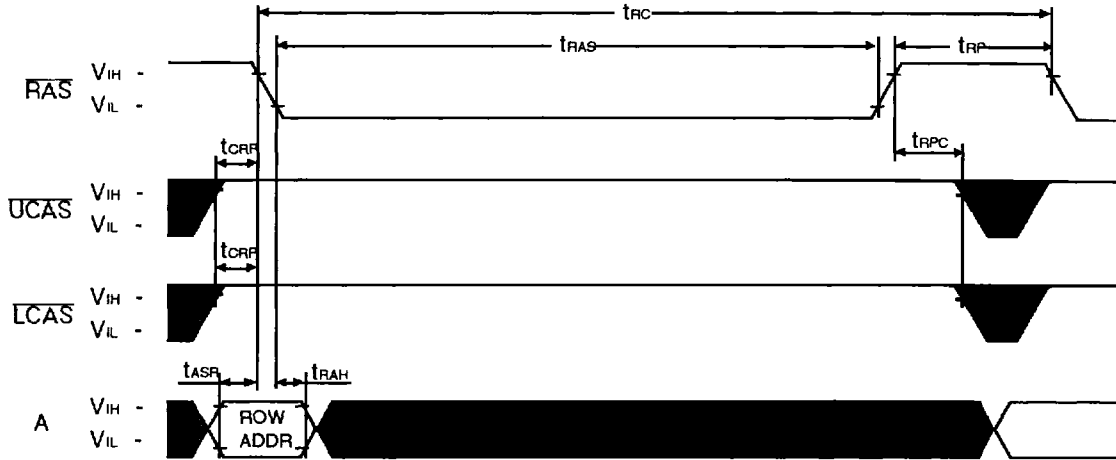


FAST PAGE MODE UPPER-BYTE-READ-MODIFY-WRITE CYCLE



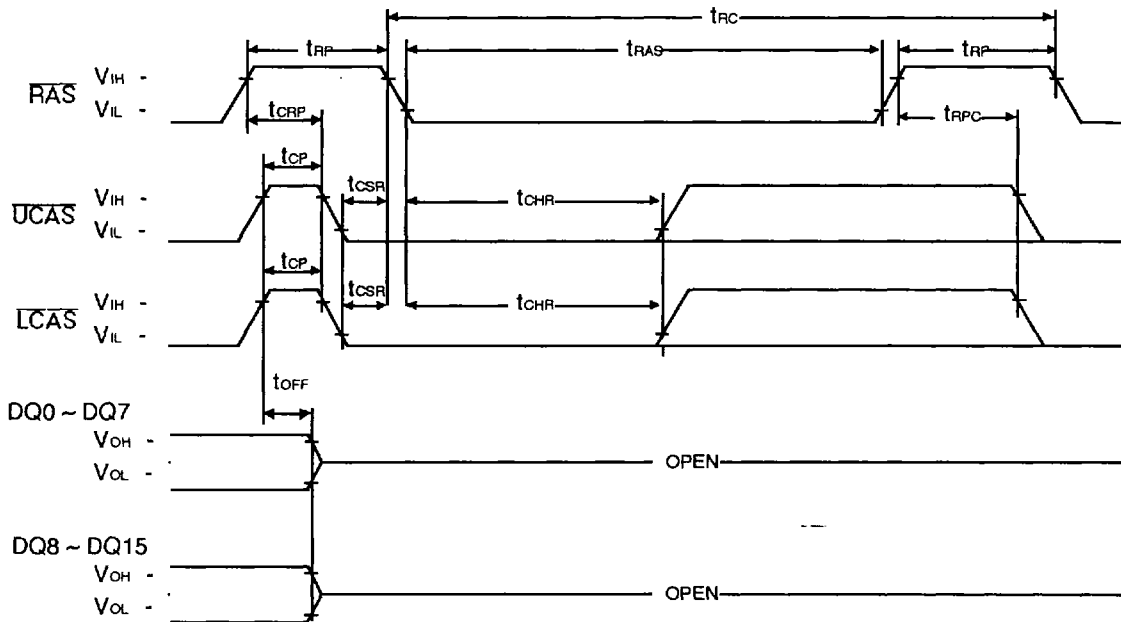
RAS-ONLY REFRESH CYCLE

NOTE : \bar{W} , \bar{OE} , D_{IN} = Don't care
 D_{OUT} = Open



CAS-BEFORE-RAS REFRESH CYCLE

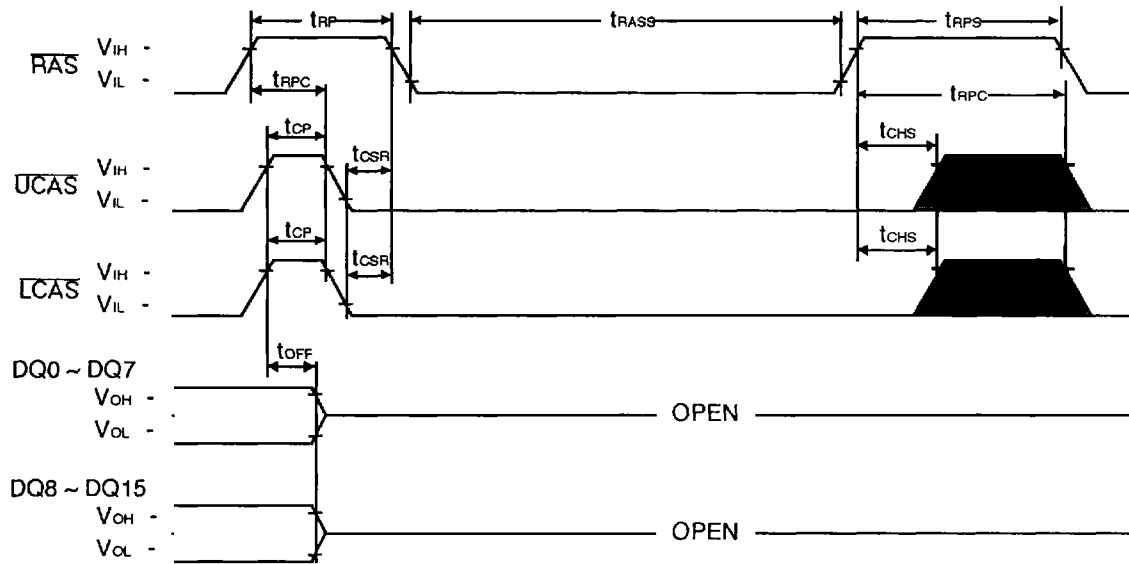
NOTE : \bar{W} , \bar{OE} , A = Don't Care



■ Don't Care

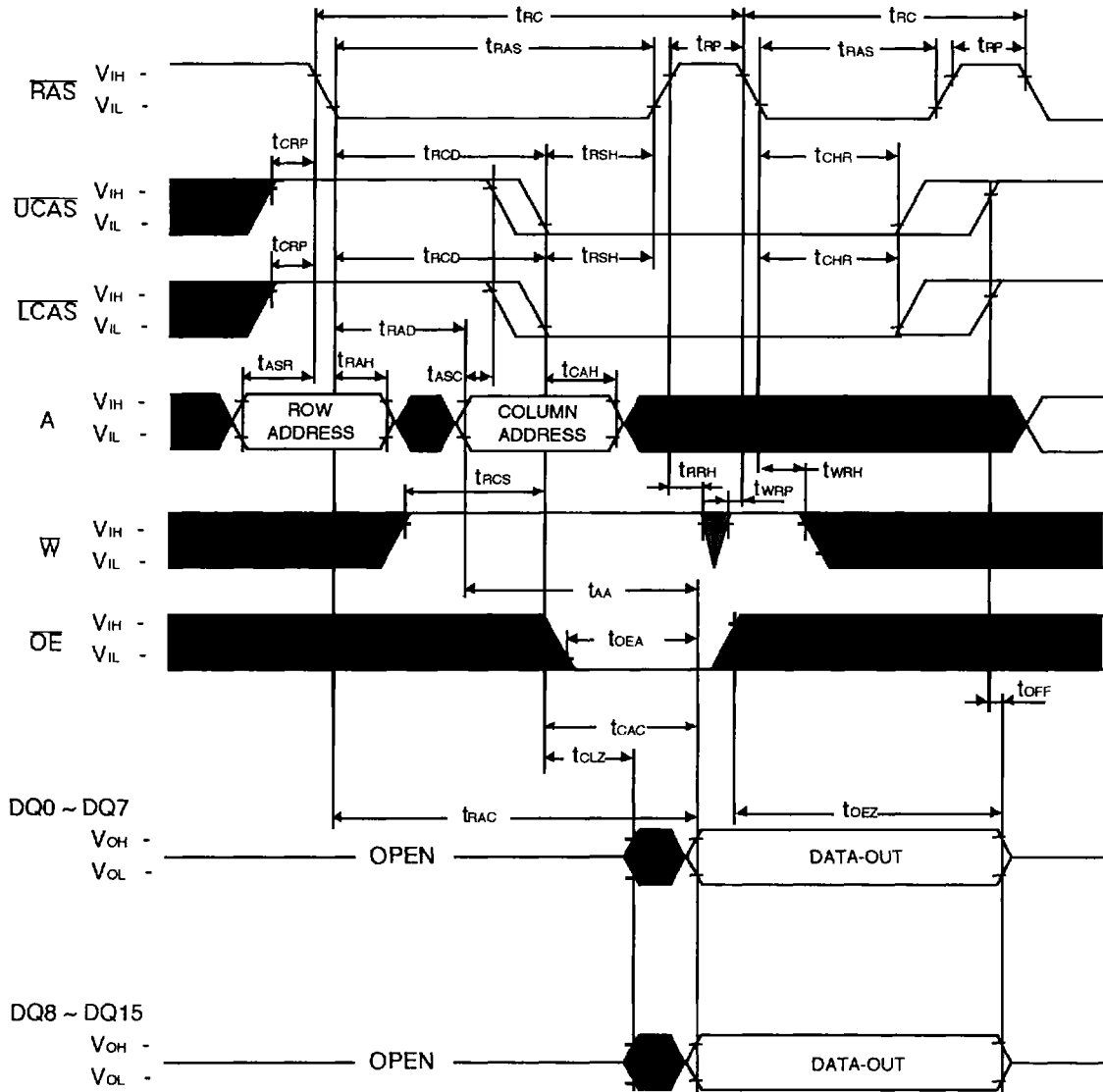
$\overline{\text{CAS}}$ -BEFORE- $\overline{\text{RAS}}$ SELF REFRESH CYCLE

NOTE : $\overline{\text{W}}$, $\overline{\text{OE}}$, A = Don't Care



■ Don't Care

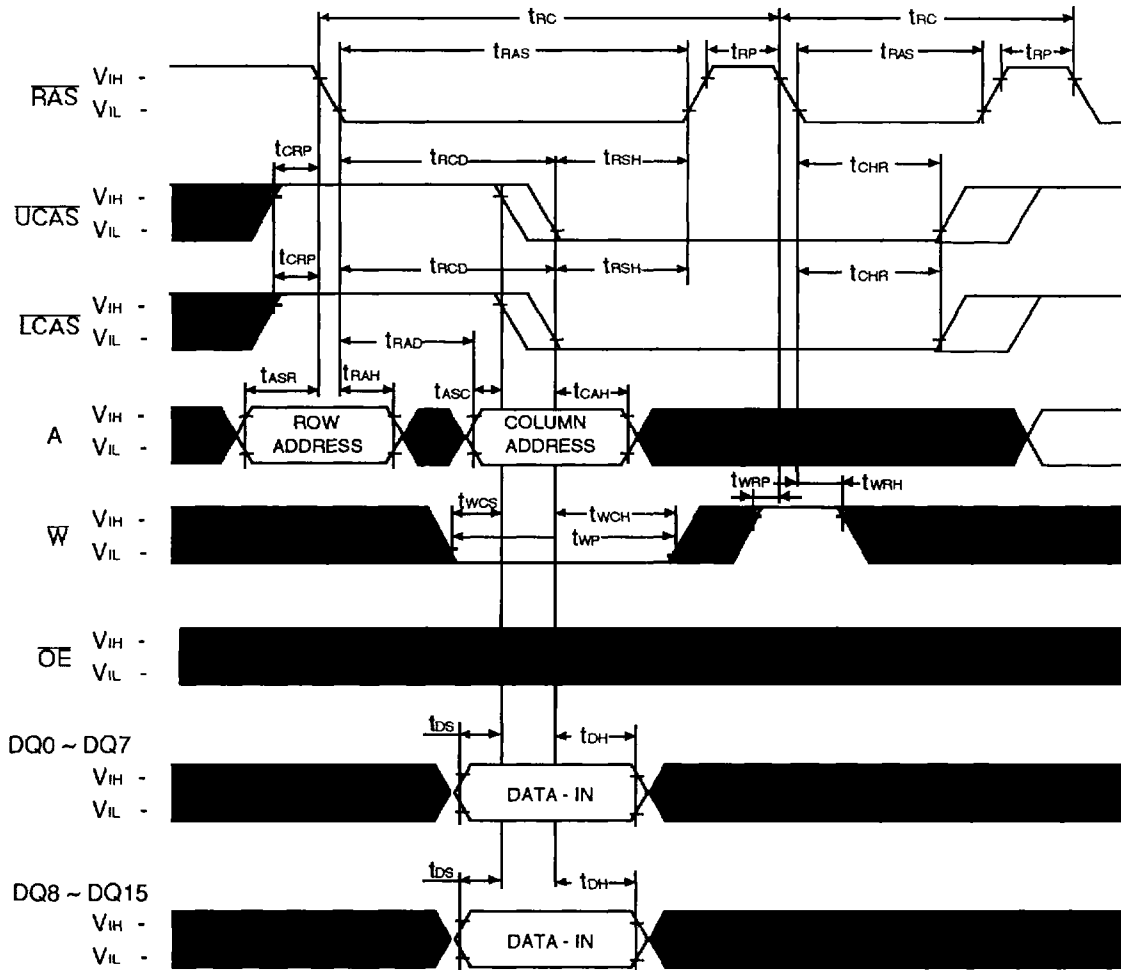
HIDDEN REFRESH CYCLE (READ)



■ Don't Care

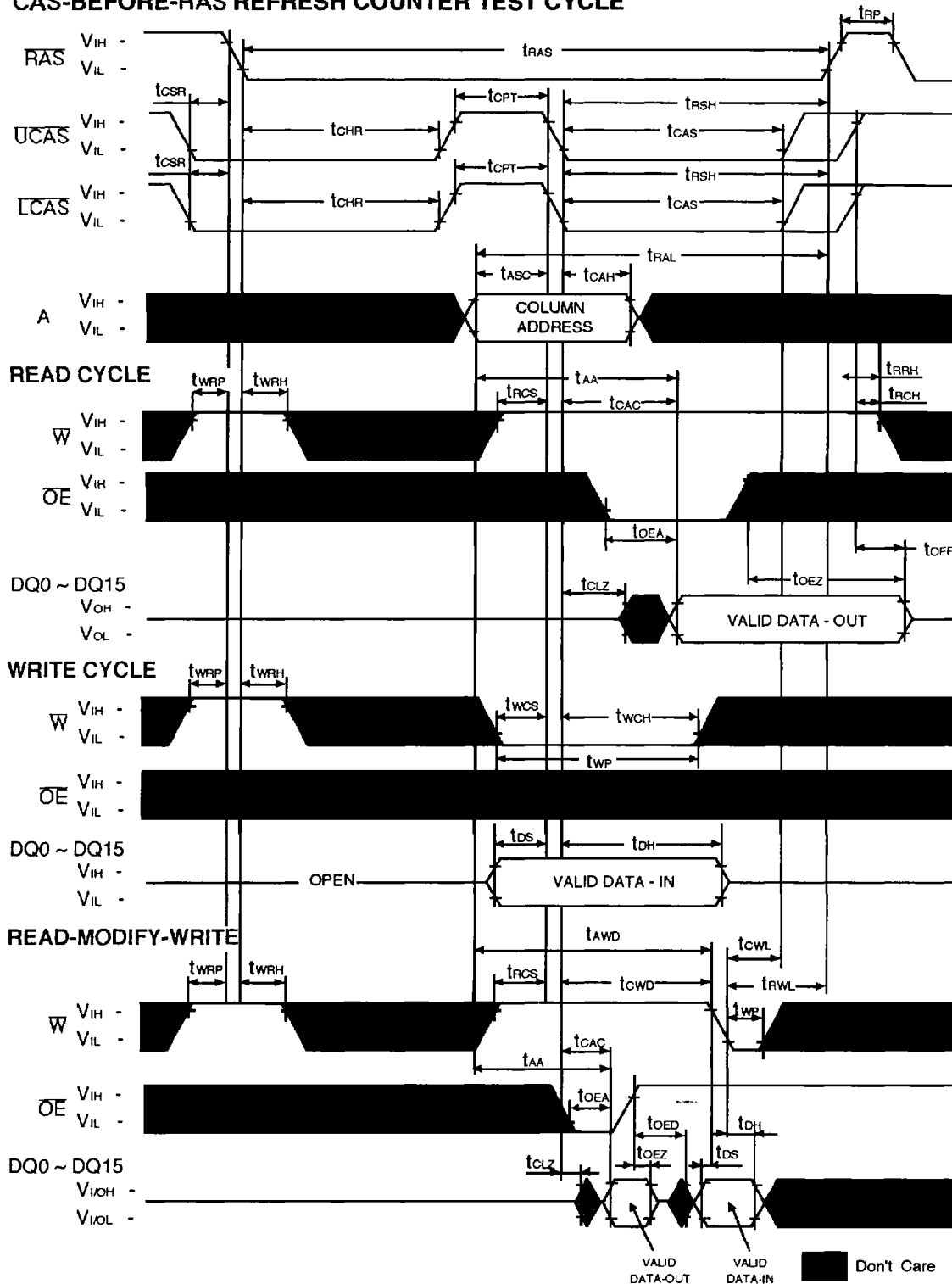
HIDDEN REFRESH CYCLE (WRITE)

NOTE : D_{OUT} = OPEN



■ Don't Care

CAS-BEFORE-RAS REFRESH CYCLE TEST CYCLE



PLASTIC SMALL OUT-LINE J-LEAD

